

CRYOGENIC CMOS DESIGN FOR SCALABLE QUBIT CONTROL AND READOUT

2025-07-16 | DR.-ING. PATRICK VLIEX

WHO AM I

Dr.-Ing. Patrick Vliex

- Studied **electrical engineering** at RWTH Aachen
 - Focus on micro- and nanoelectronics
- **IC Design** in 130 nm down to 22 nm
- PhD at Forschungszentrum Jülich (RWTH Aachen)
 - **Cryogenic electronics** for scalable solid-state QC
 - First iteration on a scalable bias voltage DAC
 - Later IC co-integrated with qubits at mK
- Currently scientific coordinator and project lead at ICA

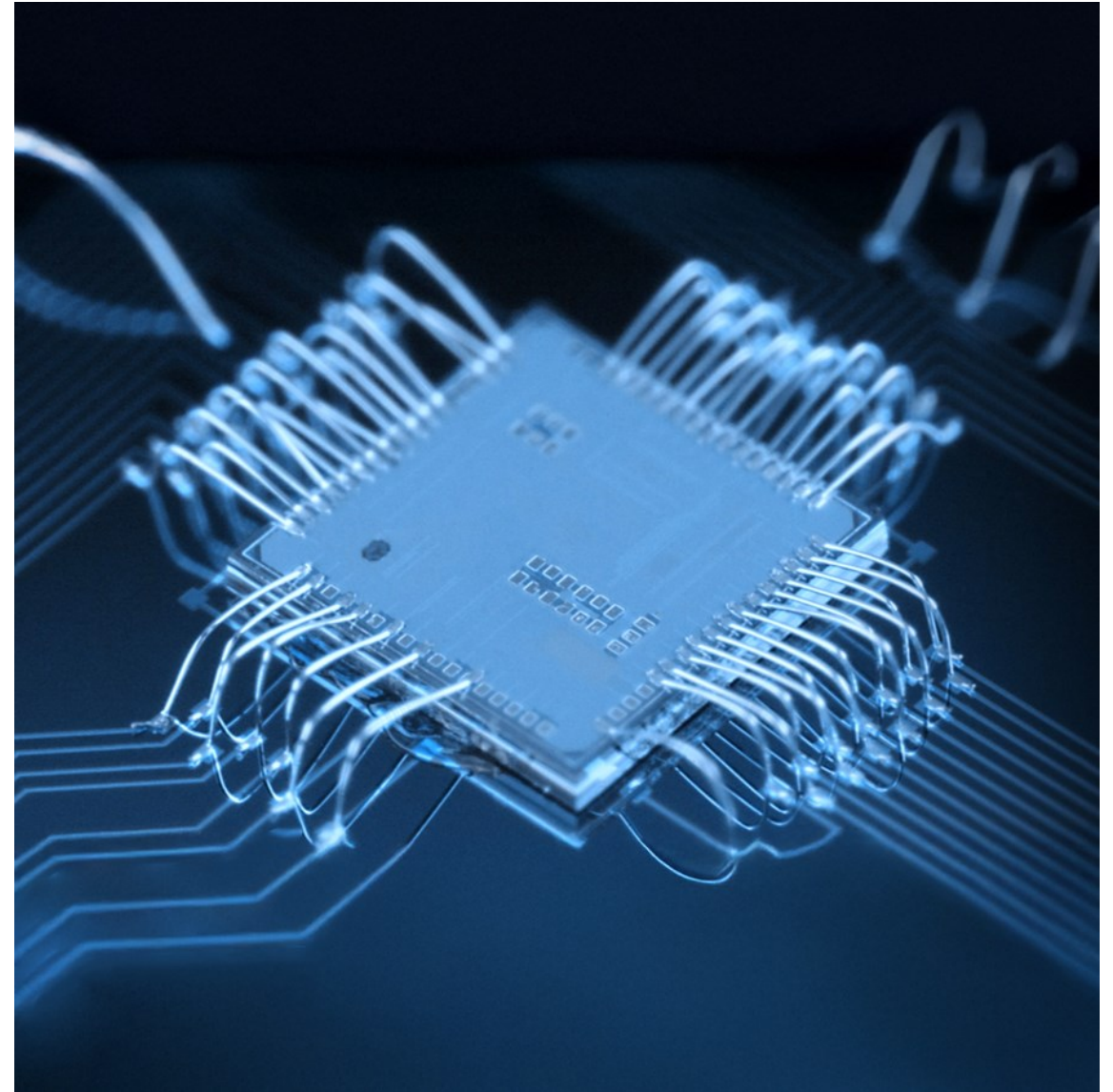


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CONTENT

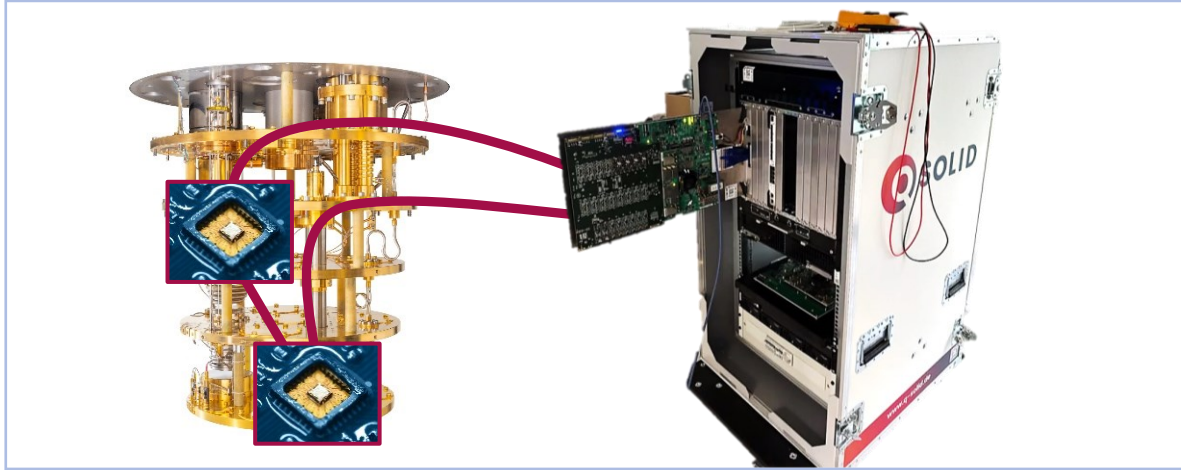
- **Designs in 65nm bulk and 22 nm FD-SOI**
 - Cryogenic measurement results
 - Lessons learned (what to watch out for)
- **Co-integration experiment with qubits at mK**
 - Thermal management
- **Other activities at ICA for QC:**
 - Cryogenic device measurement and modelling
 - Cryogenic photonic link (for superconducting qubits and cryo. electronics)



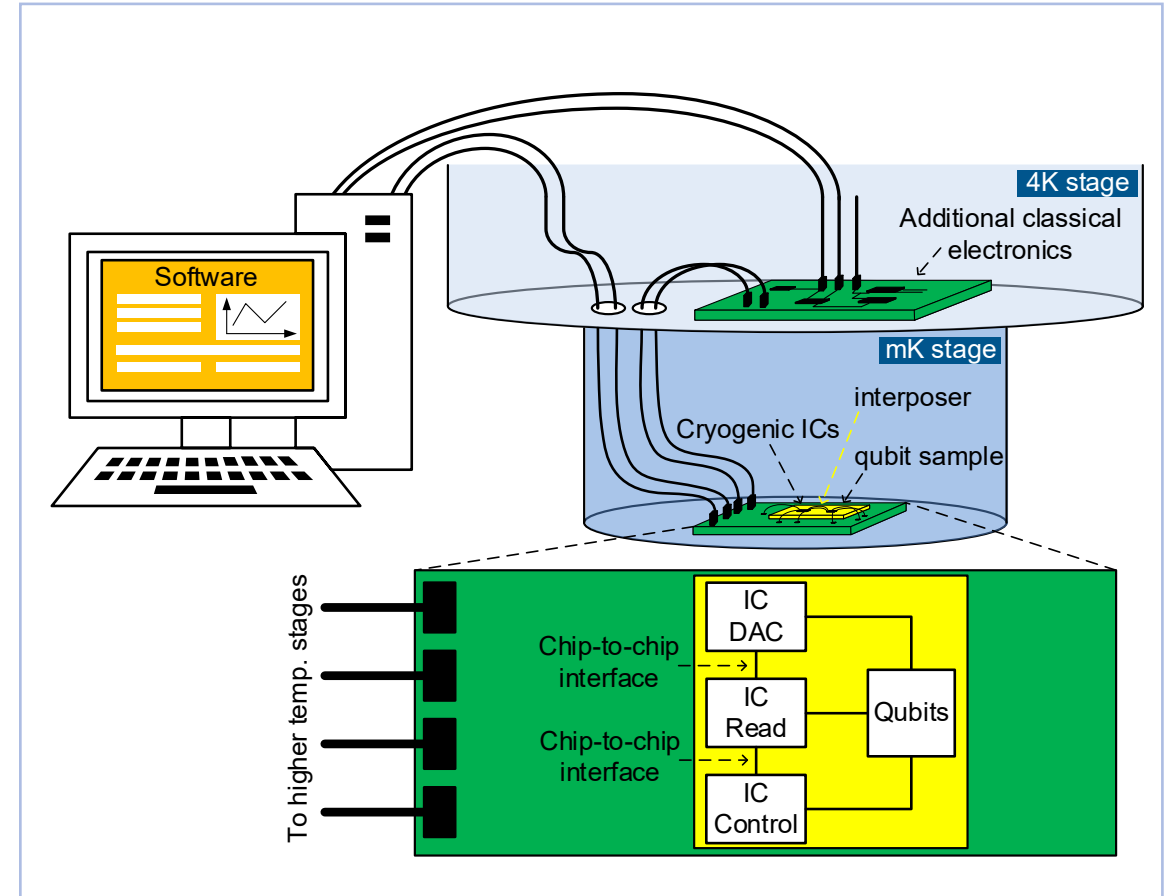
Covering the Whole Value Chain from Modeling/Specification up to System Integration



CRYOGENIC INTEGRATED CIRCUITS

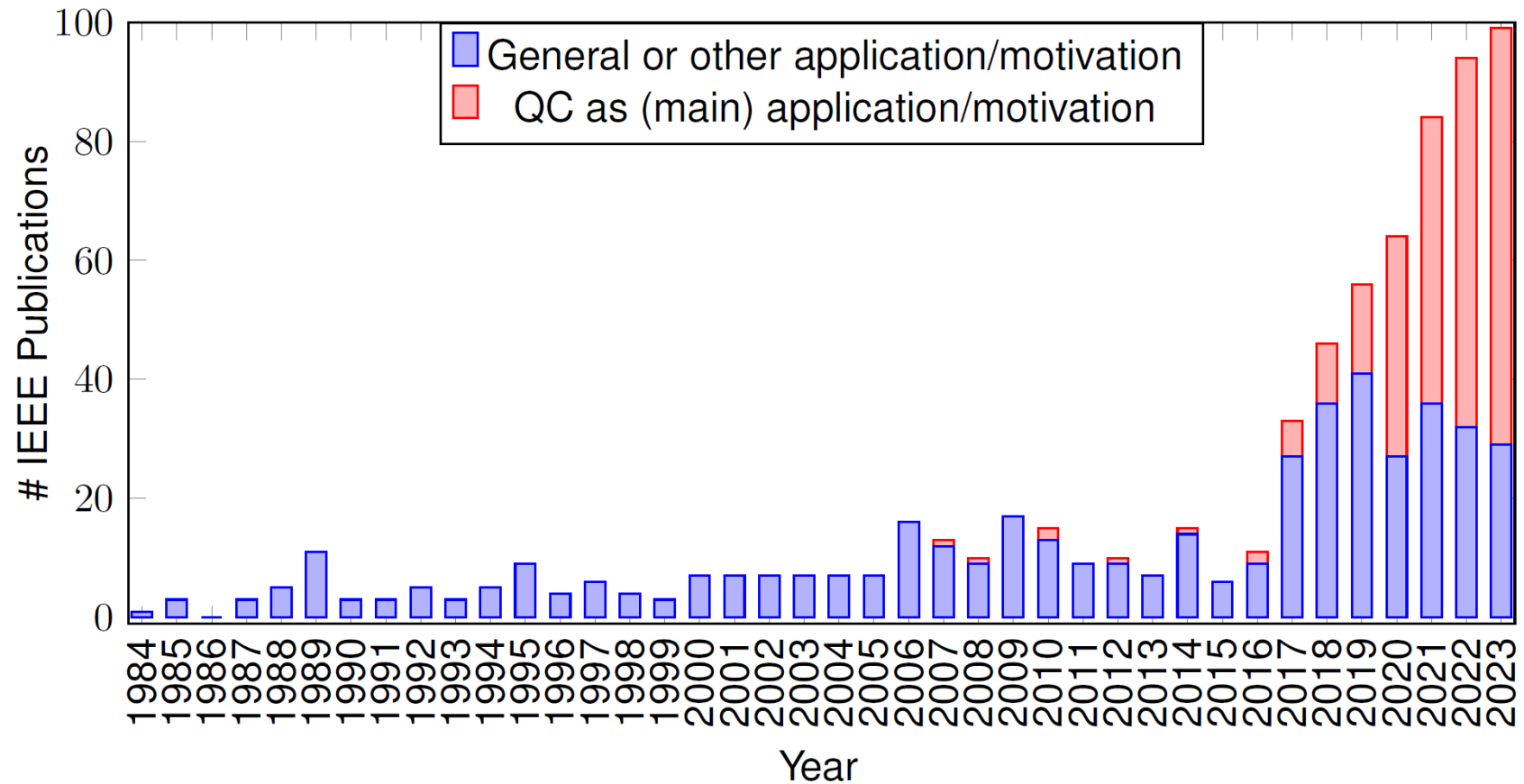


- Move (parts) of classical control & readout electronics closer to the qubit
- Consequence → operate at cryogenic temperature
- Cryogenic CMOS enables high-integration
 - Comply to ultra strict cooling power budget
- Qubits are evolving quickly → modular IC framework



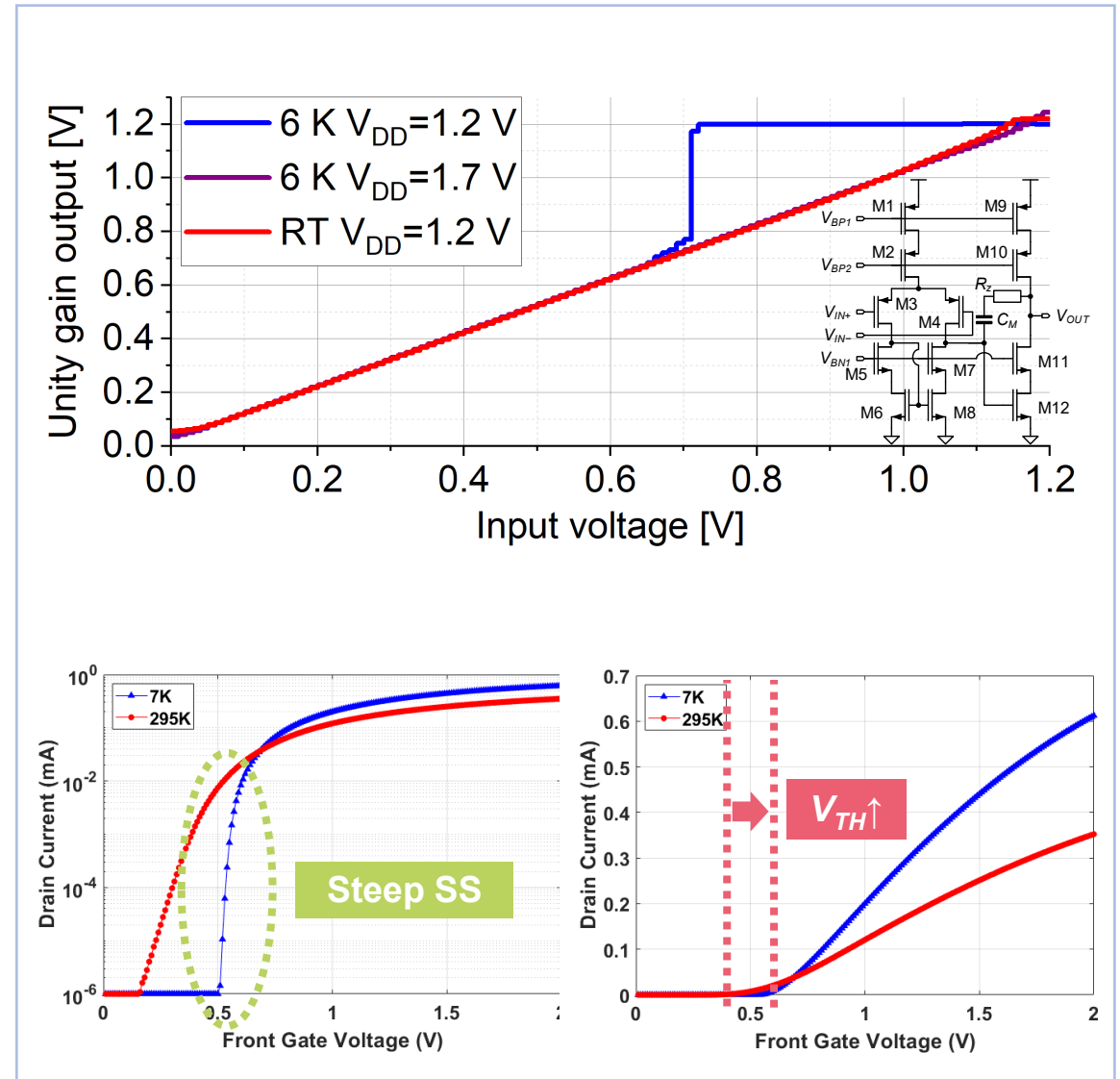
CRYOGENIC INTEGRATED CIRCUITS

In the Spotlight



OPAMP

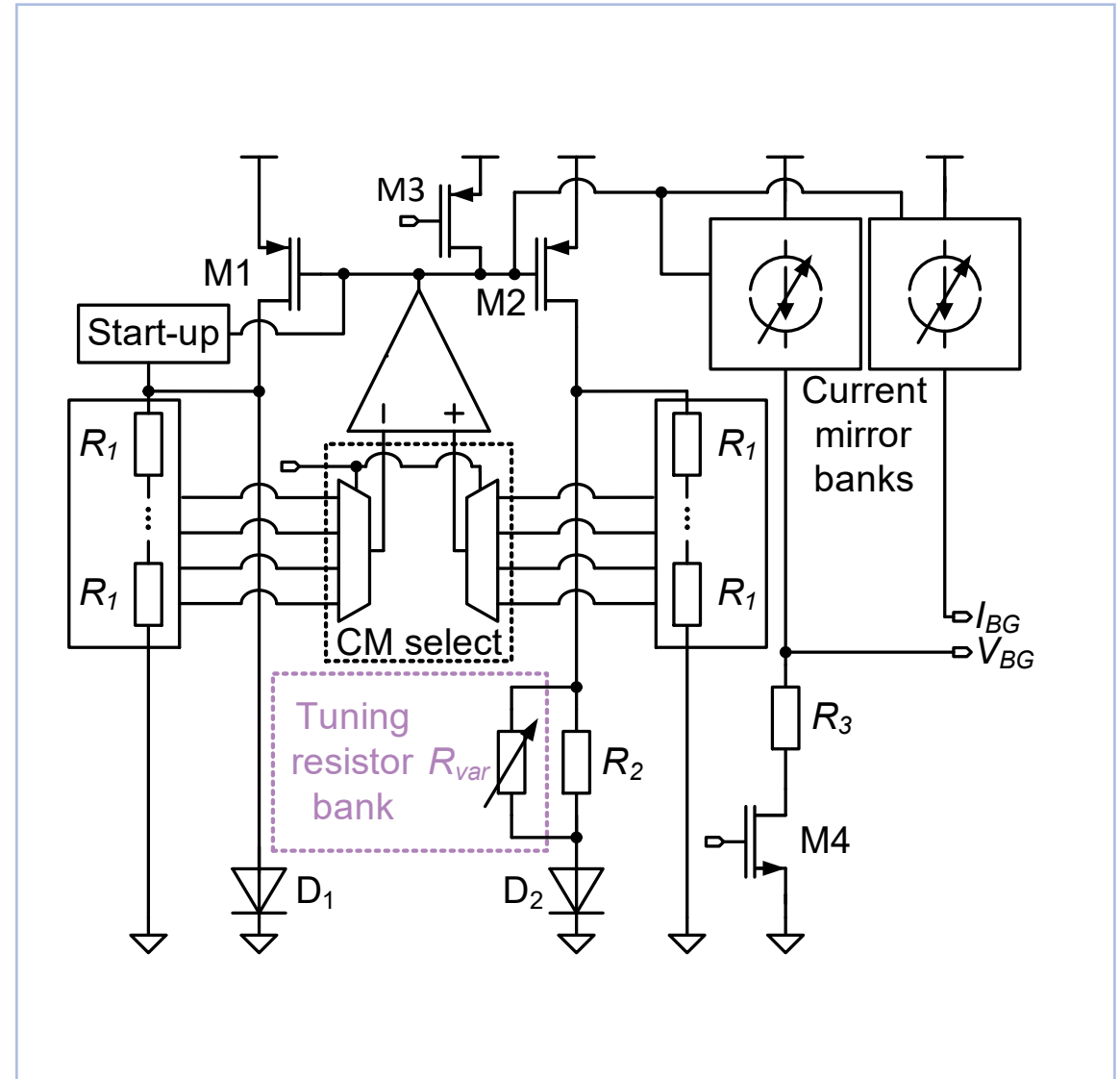
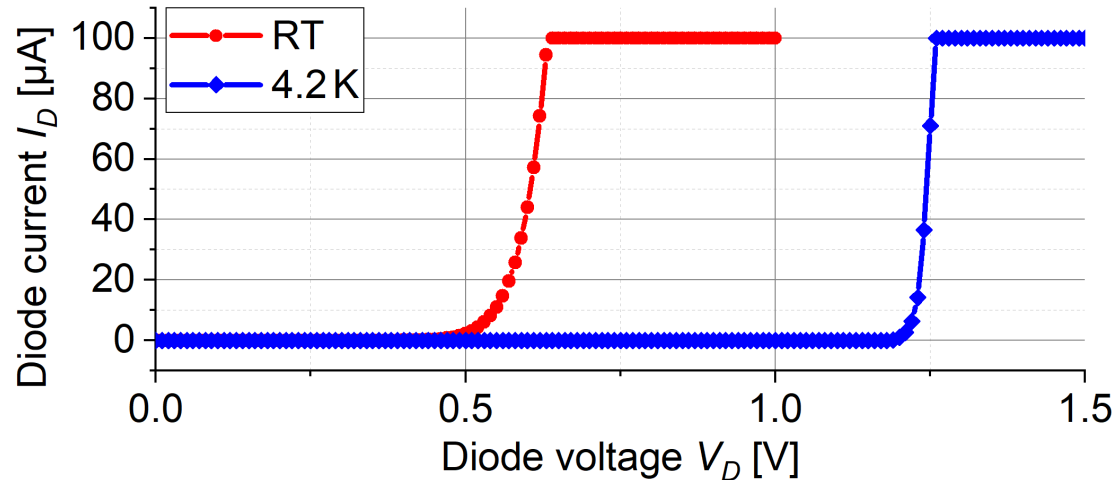
- Clipping of Opamp output at cryo temp.
 - No subthreshold operation possible
 - Due to steep SS
- Increase supply for extra headroom
 - Use **low supply circuit topologies**
- **Pay extra attention to stay in strong inversion**
 - Compensate or be aware of V_{TH} shift



BANDGAP

Design

- Current-mode topology^[1] in 65 nm bulk CMOS
- Tuning options for cryogenic temperature
- Diode behavior at room temp. (RT) and 4.2 K

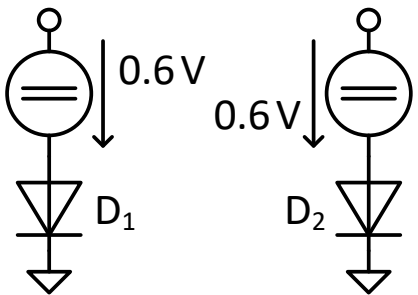


[1] H. Banba et al. "A CMOS bandgap reference circuit with sub-1-V operation". In: IEEE Journal of Solid-State Circuits 34.5 (May 1999), pp. 670–674. doi: 10.1109/4.760378.

BANDGAP

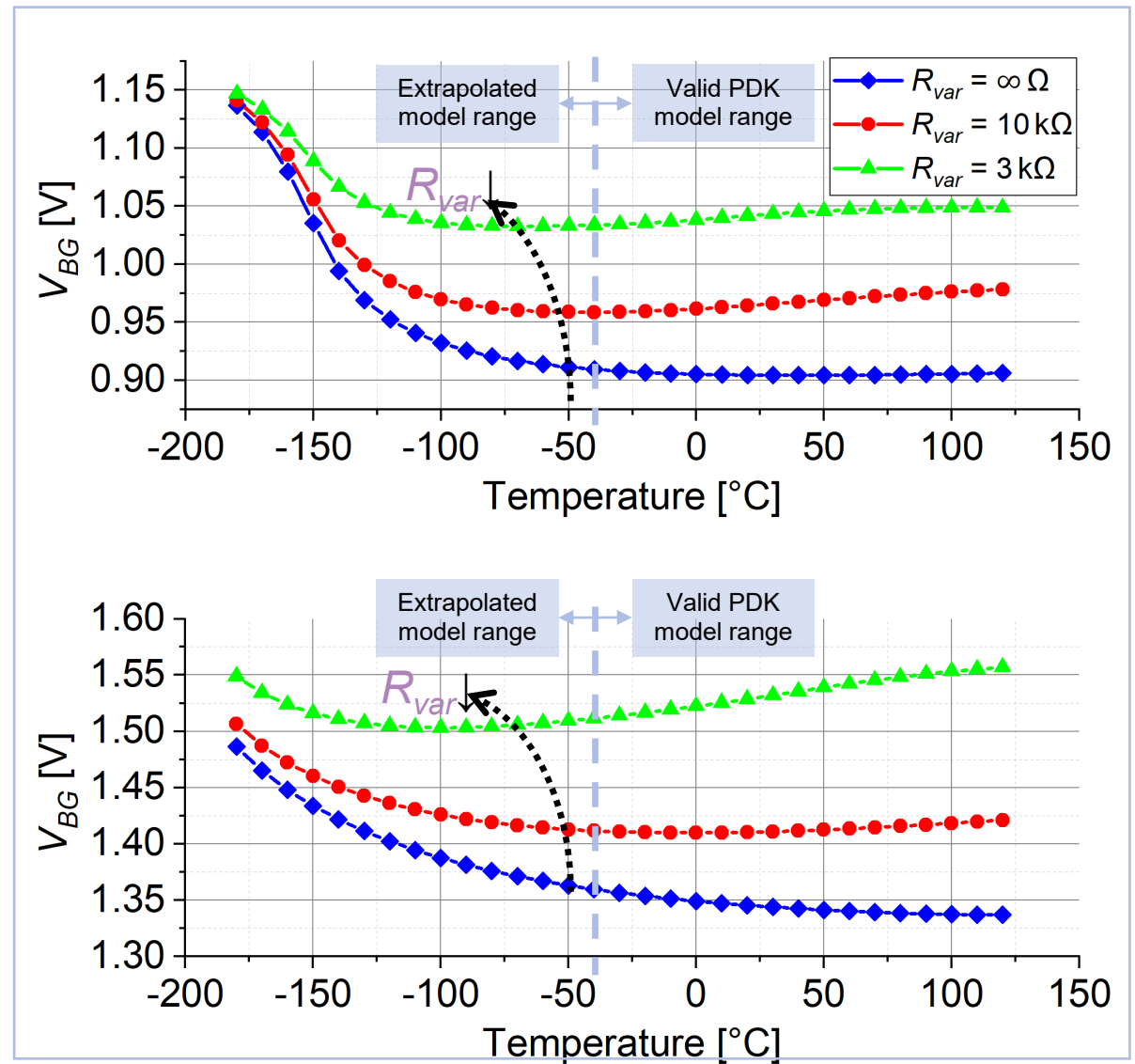
Simulation Results

- PDK valid from $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$
- Cryo V_{TH} increase of D_1 and $D_2 \approx 0.6\text{ V}$
 - Modeled by added voltage sources
 - V_{DD} increase required: $1.2\text{ V} \rightarrow 1.8\text{ V}$



Added sources

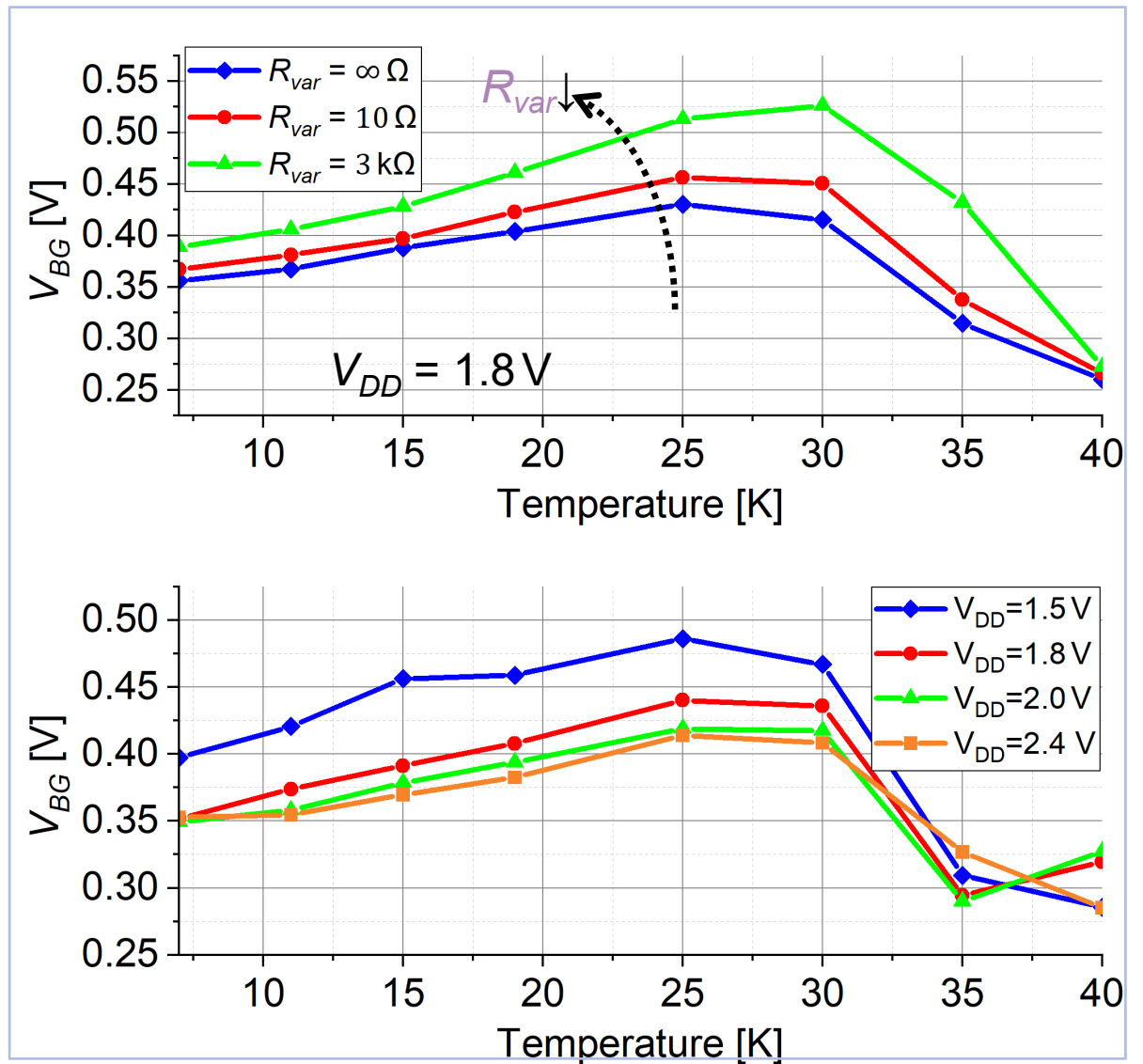
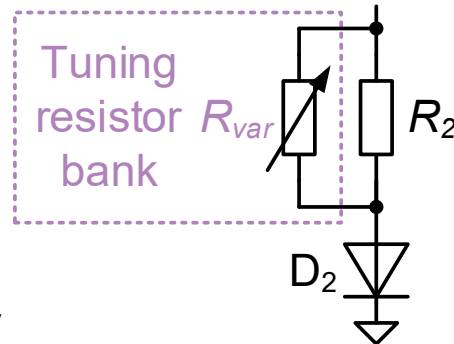
V_{DD} increased



BANDGAP

Measurement

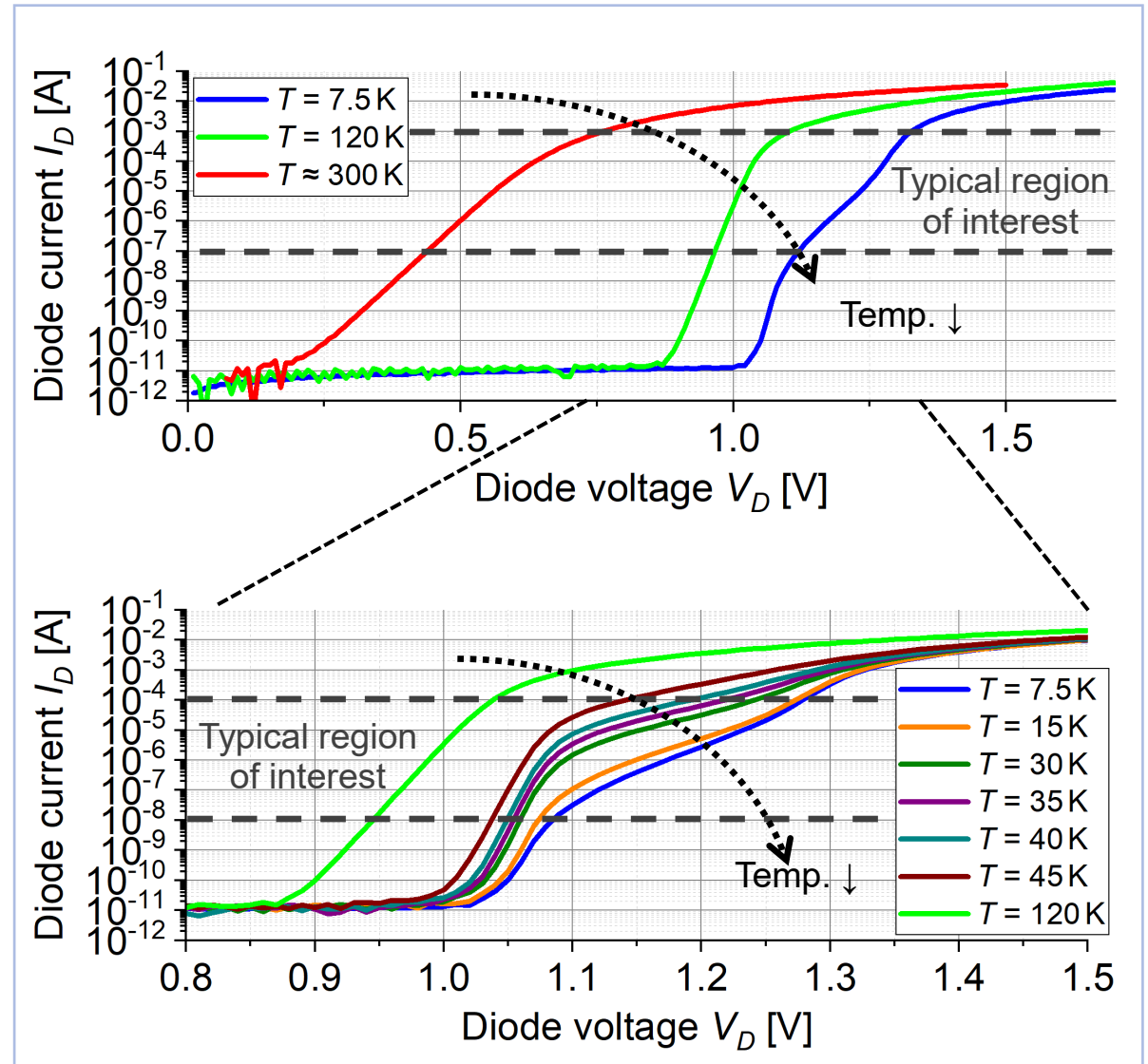
- BG curve is tilted like desired by R_{var}
 - V_{BG} curvature is „convex“
 - Contradicting all simulation results
- In order to improve temp. compensation
 - Need to increase R_2
 - Set $R_{var} \rightarrow \infty \Omega$
- BG sweetspot at $V_{DD} = 1.8 \text{ V}$
 - Well operating & min. power
- Notable kink at temp. 35 K



BANDGAP

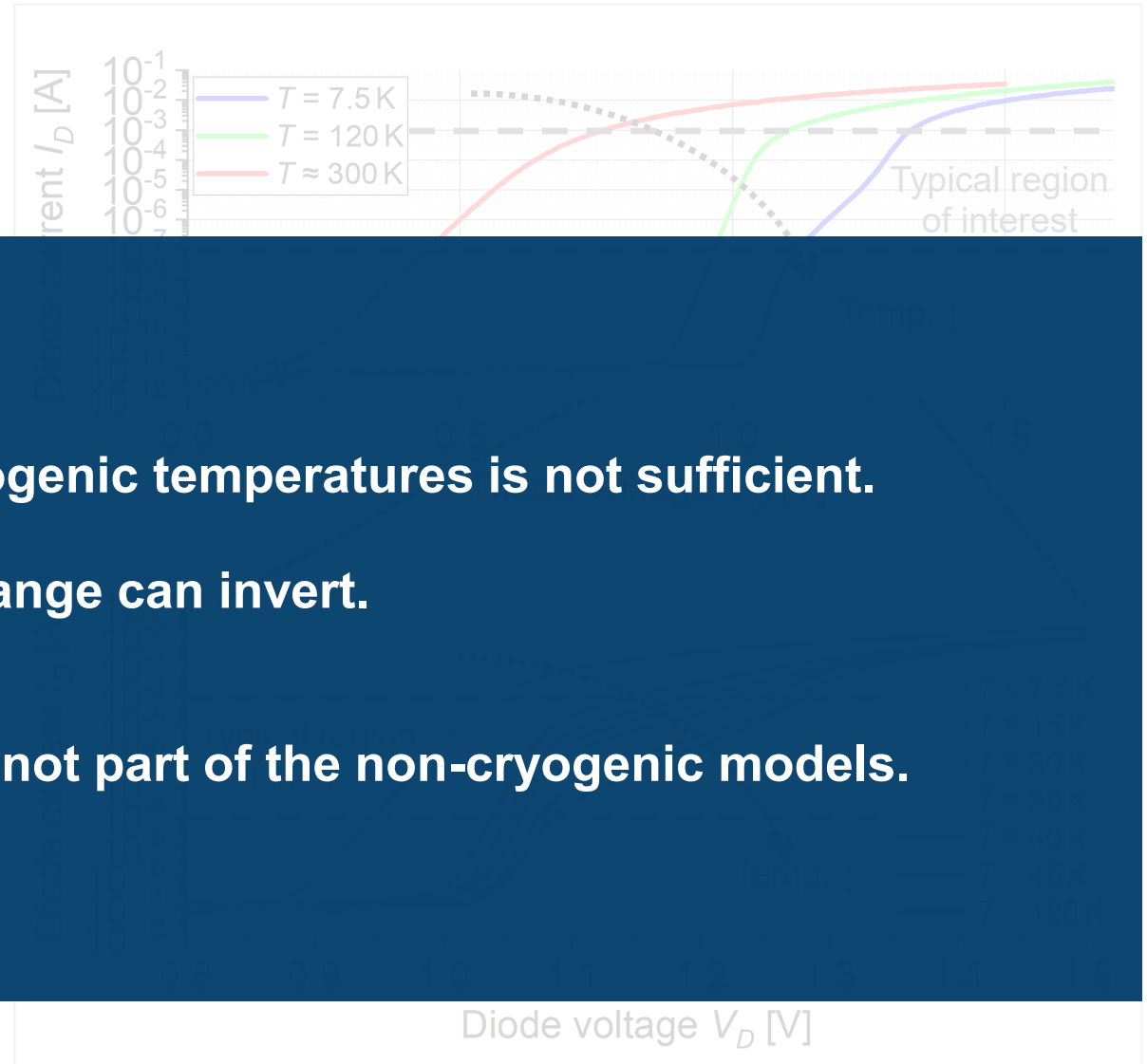
Measurement

- Steeper diode slope with reduced temperature
Kink apparent for cryo. temperature
- Notable for temperature $T \lesssim 40$ K
 - Flattening the curve in the typical region of interest (100 nA to 100 μ A)
 - Transition from no-kink to kink
- BG output V_{BG} kink also at 35 K
- BG design requires dedicated diode models and understanding for cryo.



BANDGAP

Measurement



Extrapolating trends from RT to cryogenic temperatures is not sufficient.

Direction of change can invert.

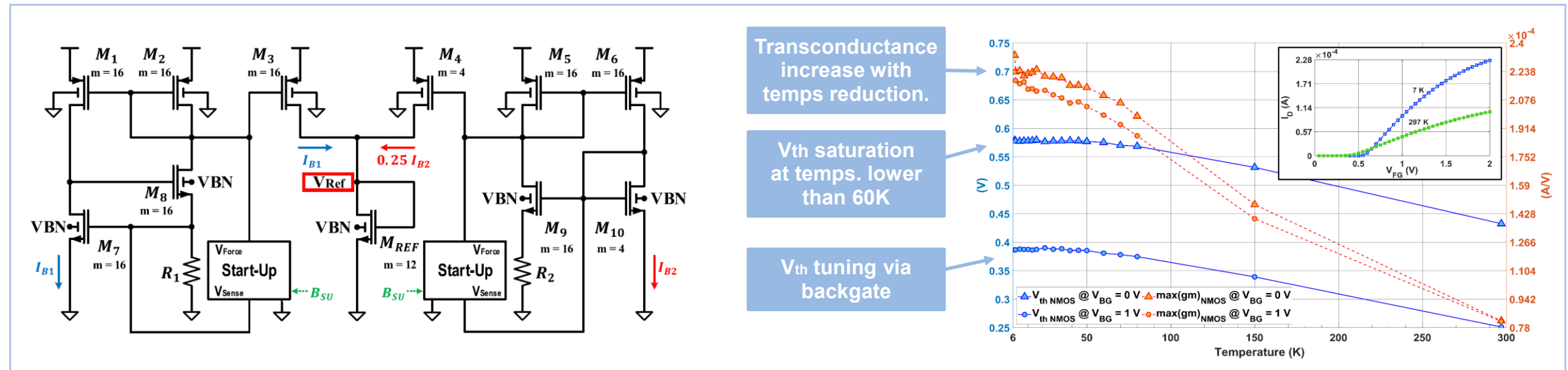
New effects come into play which are not part of the non-cryogenic models.

CRYOGENIC INTEGRATED CIRCUITS

Voltage Reference in 22nm FD-SOI



- Cryogenic V_{TH} saturation as working principle
- The circuit saturates M_{REF} while in V_{TH} saturation temperature region
- Simple and without post-fabrication correction
→ **Utilize transistor effects in cryo!**



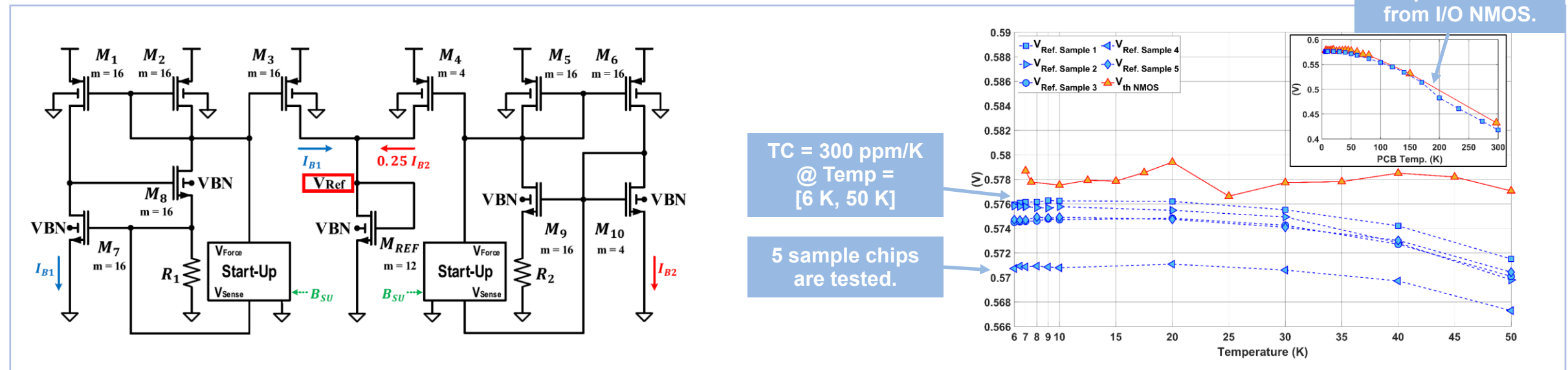
[2] A. R. Cabrera-Galicia, et.al, "Voltage Reference and Voltage Regulator for the Cryogenic Performance Evaluation of the 22nm FDSOI Technology," in IEEE Open Journal of Circuits and Systems, vol. 5, pp. 377-386, 2024, doi: 10.1109/OJCS.2024.3466395

CRYOGENIC INTEGRATED CIRCUITS

Voltage Reference in 22nm FD-SOI



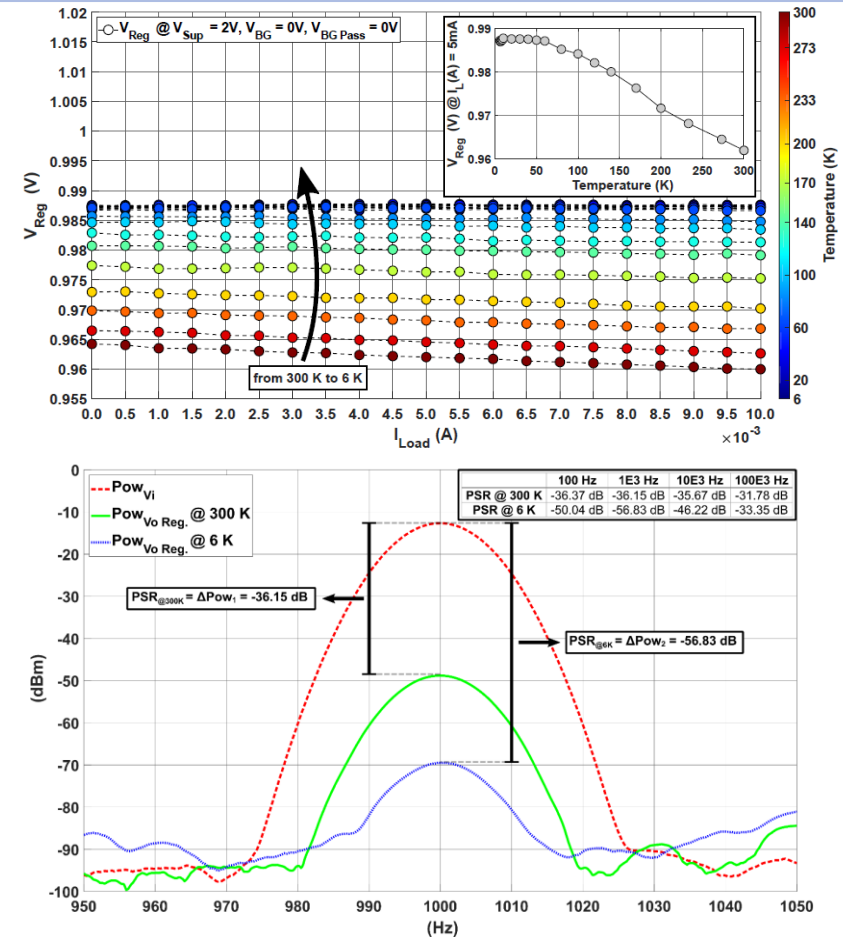
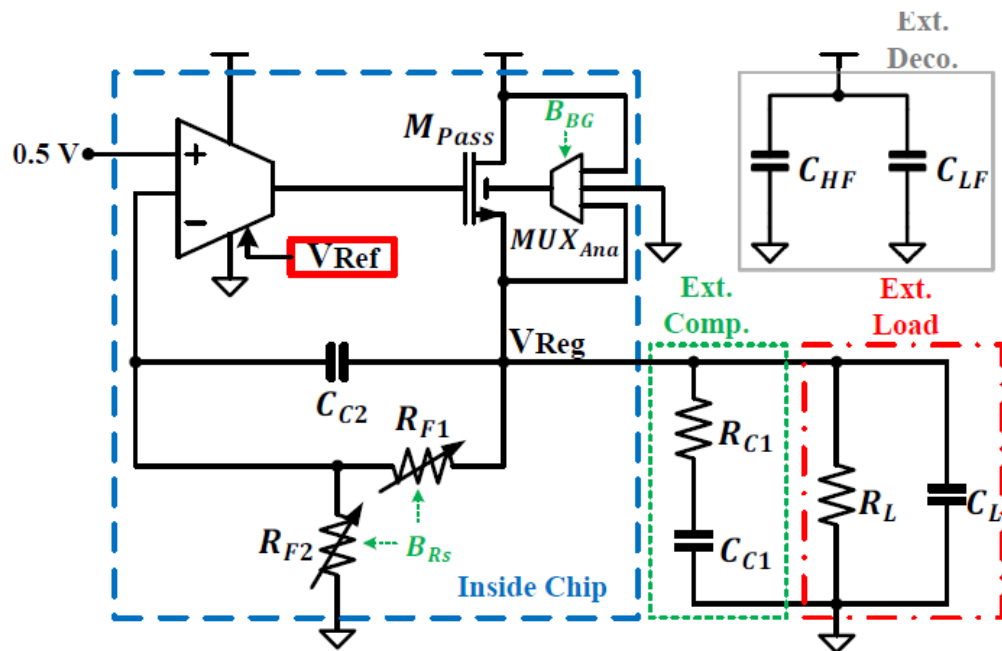
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[2] A. R. Cabrera-Galicia, et.al, "Voltage Reference and Voltage Regulator for the Cryogenic Performance Evaluation of the 22nm FDSOI Technology," in IEEE Open Journal of Circuits and Systems, vol. 5, pp. 377-386, 2024, doi: 10.1109/OJCS.2024.3466395

CRYOGENIC INTEGRATED CIRCUITS

Voltage Reference and Regulator Circuit in 22nm FD-SOI

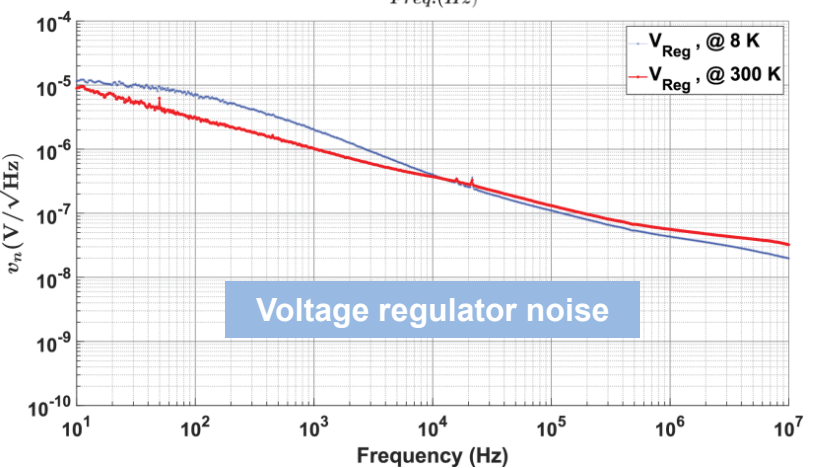
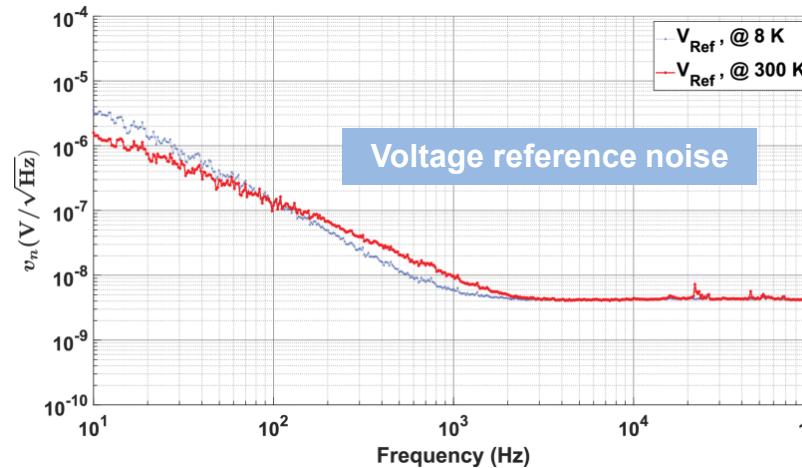
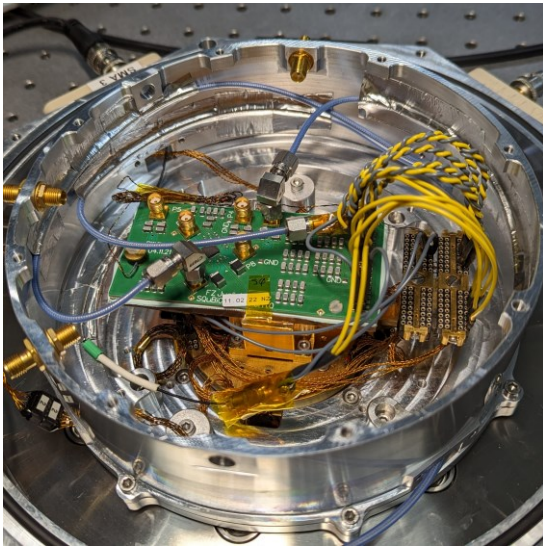


[2] A. R. Cabrera-Galicia, et.al, "Voltage Reference and Voltage Regulator for the Cryogenic Performance Evaluation of the 22nm FDSOI Technology," in IEEE Open Journal of Circuits and Systems, vol. 5, pp. 377-386, 2024, doi: 10.1109/OJCS.2024.3466395

NOISE

Cryostat and Voltage Reference & Regulator

- Avoid GND loops in the cryostat
 - Counteracting the wish to thermal couple
- Increased 1/f noise; decreased thermal noise



Ground loop noise is coupled to regulator output via cold plate.

Ground loop noise is removed by electrically detaching the regulator from the cold plate.

Higher temp. due to thermal pad and imperfect thermalization of cables; improvement on progress.

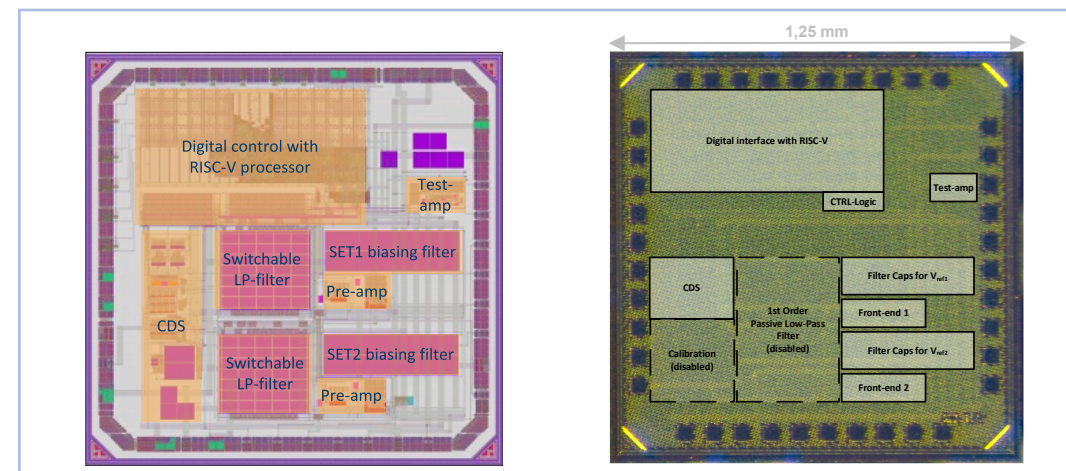
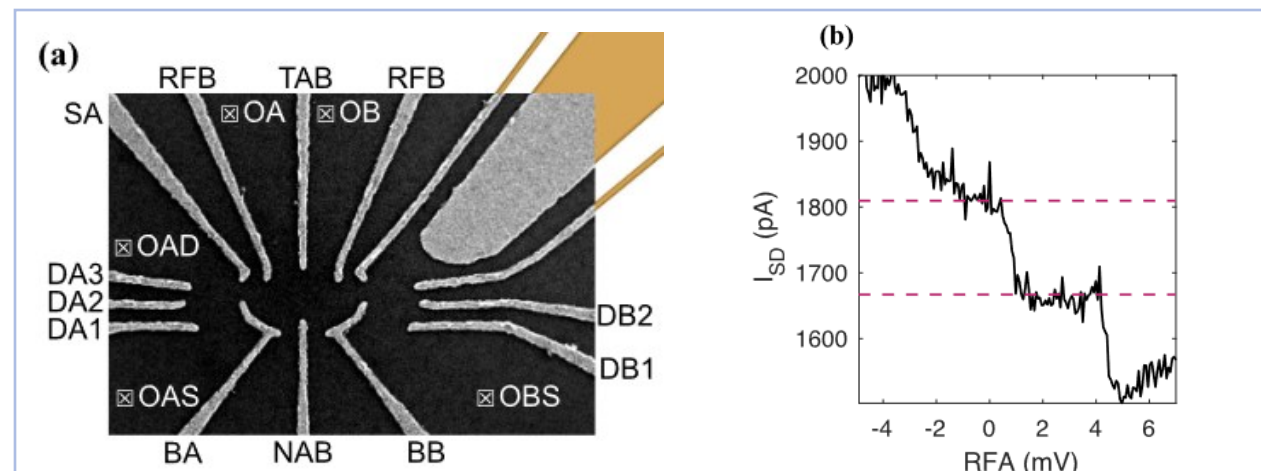
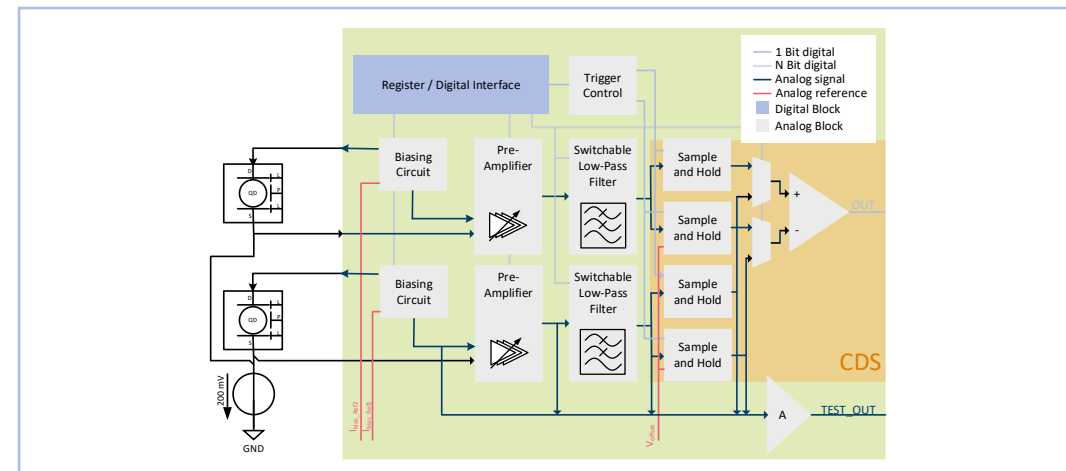
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CRYOGENIC INTEGRATED CIRCUITS



Qubit Readout - QUOCCA.SET: A Scalable Readout IC for Semiconductor Quantum Dots

- **Target: readout of quantum dots**
- Pauli spin blockade to convert spin to charge
- Single electron transistor (SET) to convert charge to current (signal ca. 250 pA)



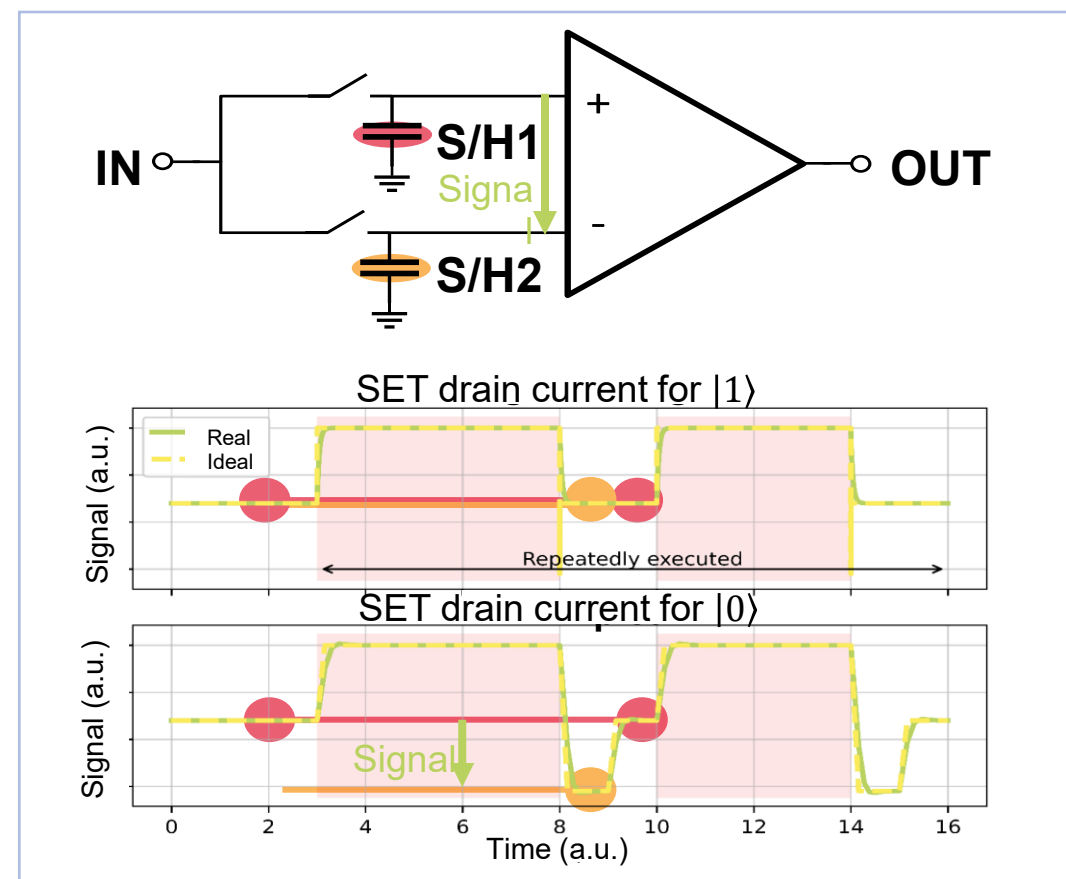
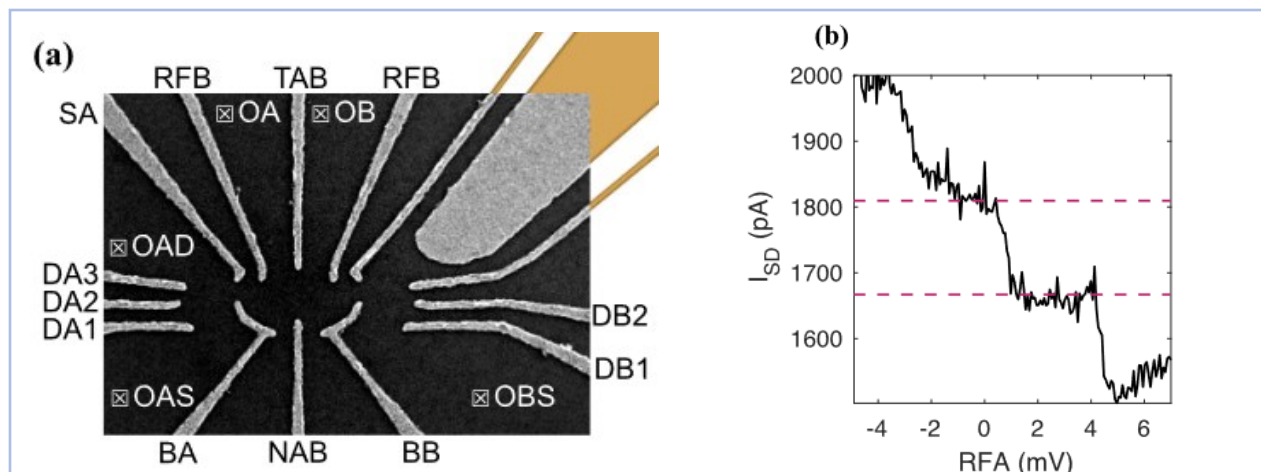
[3] J.Buehler et al., "QUOCCA.SET: A Scalable Readout IC for Semiconductor Quantum Dots", Global Physics Summit 2025, MAR-G19/4

CRYOGENIC INTEGRATED CIRCUITS



Qubit Readout - QUOCCA.SET: A Scalable Readout IC for Semiconductor Quantum Dots

- **Correlated Double Sampling (CDS)**
 - 1st sample after qubit initialization
 - 2nd sample after qubit operation
 - Cancellation of low frequency noise



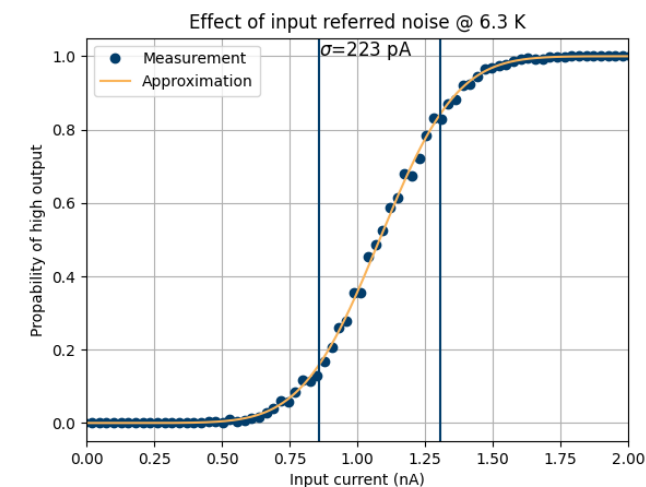
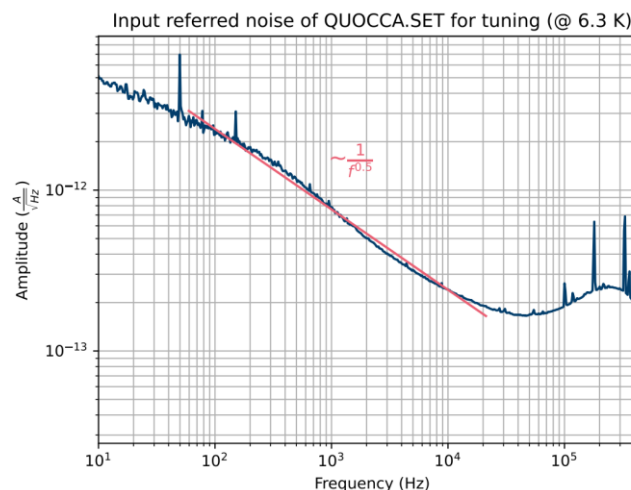
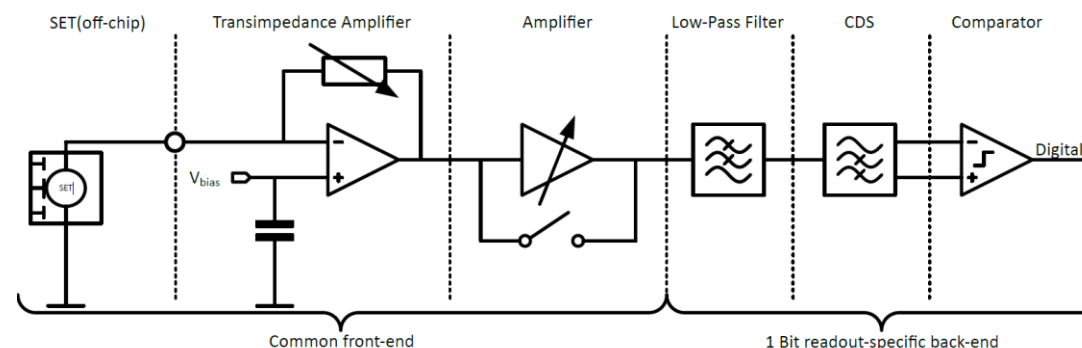
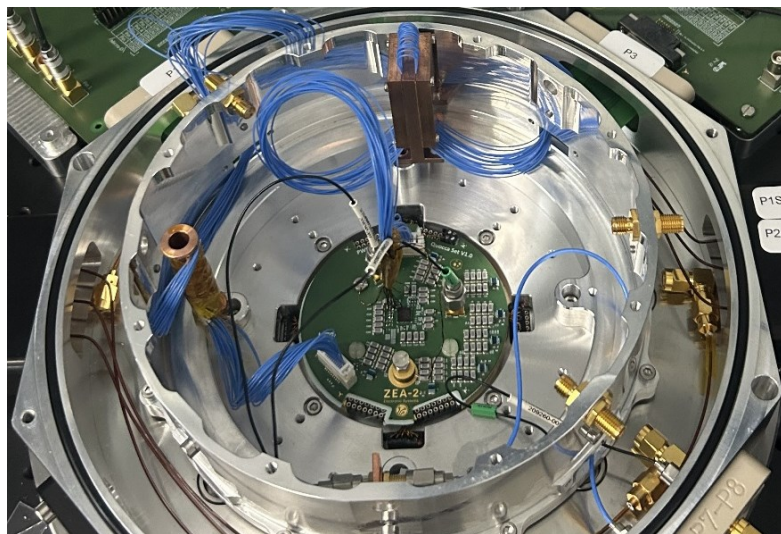
[3] J.Buehler et al., "QUOCCA.SET: A Scalable Readout IC for Semiconductor Quantum Dots", Global Physics Summit 2025, MAR-G19/4

CRYOGENIC INTEGRATED CIRCUITS



Qubit Readout - QUOCCA.SET: A Scalable Readout IC for Semiconductor Quantum Dots

- 223 pA RMS @ 1 μ s, max. BW
- 111 pA RMS @ 1 μ s, 1 kHz BW
- Digital Power: 41 μ W
- Analog Power: 33.6 μ W/SET



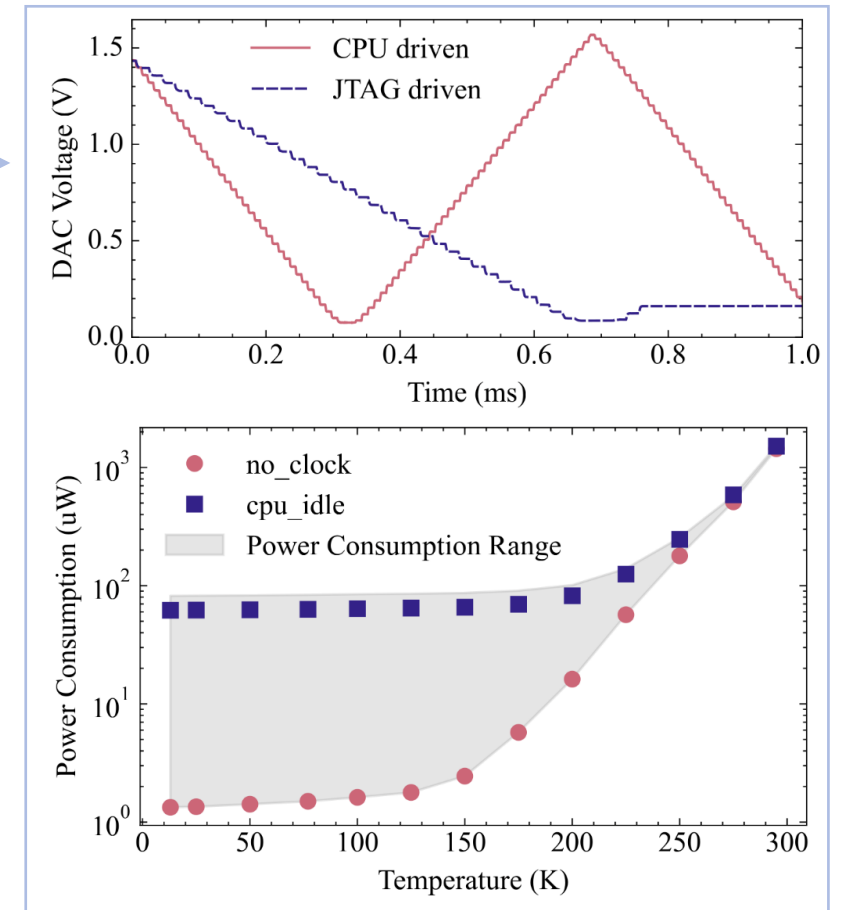
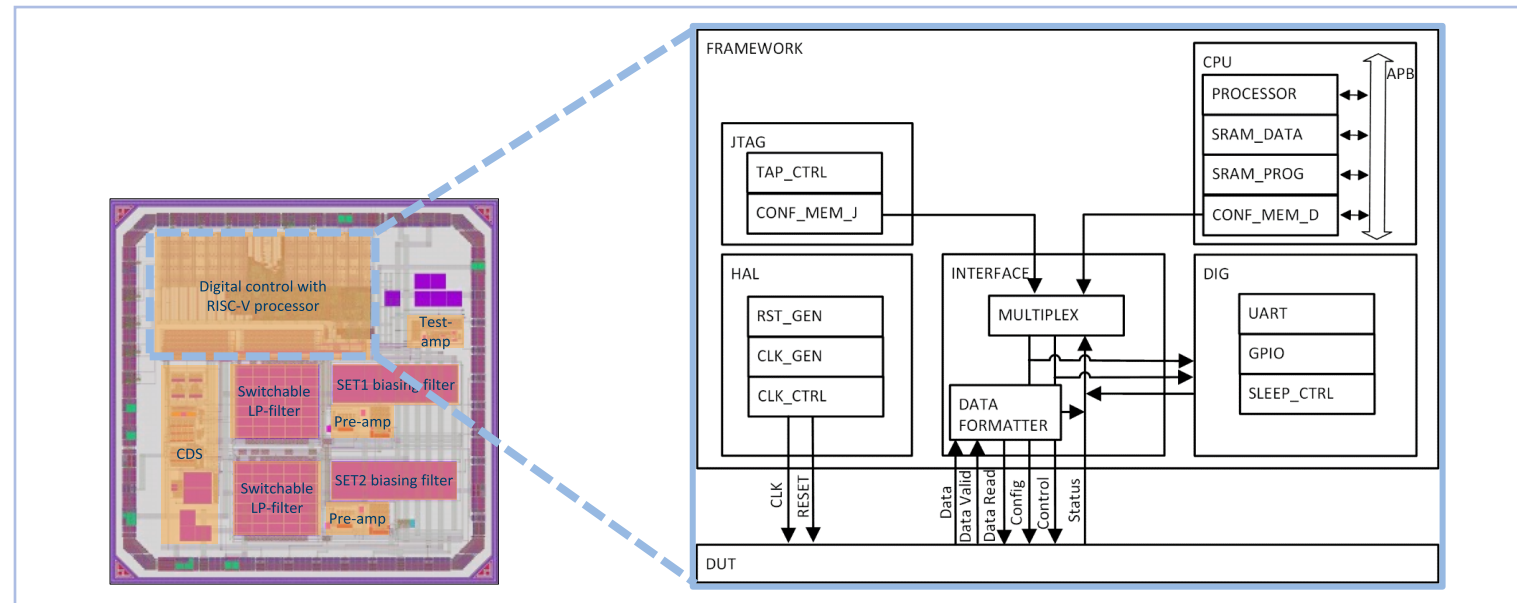
[3] J.Buehler et al., "QUOCCA.SET: A Scalable Readout IC for Semiconductor Quantum Dots", Global Physics Summit 2025, MAR-G19/4

INTEGRATED RISC-V

Rapid Prototyping Platform for Integrated Circuits for Quantum Computing



- RISC-V with SRAM and APB
- Enables flexibility in control (algorithms)
- Leakage negligible at cryo



[4] J. Mair et al., "Rapid Prototyping Platform for Integrated Circuits for Quantum Computing," 2024 20th International Conference on Synthesis, Modeling, Analysis and Simulation Methods and Applications to Circuit Design (SMACD), Volos, Greece, 2024, pp. 1-4, doi: 10.1109/SMACD61181.2024.10745395.

DIGITAL INTERFACE

Comparison of Industry Standard Protocols

Protocol	Pro 😊	Cons ☹️
UART	2-wire interface (RX TX) No pull-up/down	Requires sync.
I ² C	2-wire interface (SDA SCL)	Pull-ups
SPI	No pull-up/down	3[4]-wire interface (SCLK MOSI MISO [CE])
JTAG	No pull-up/down	4-wire interface (TCK TMS TDI TDO) Complex state-machine
cJTAG	2-wire interface (TCKC TMSC)	Complex state-machine Less established Optional Pull-ups/downs

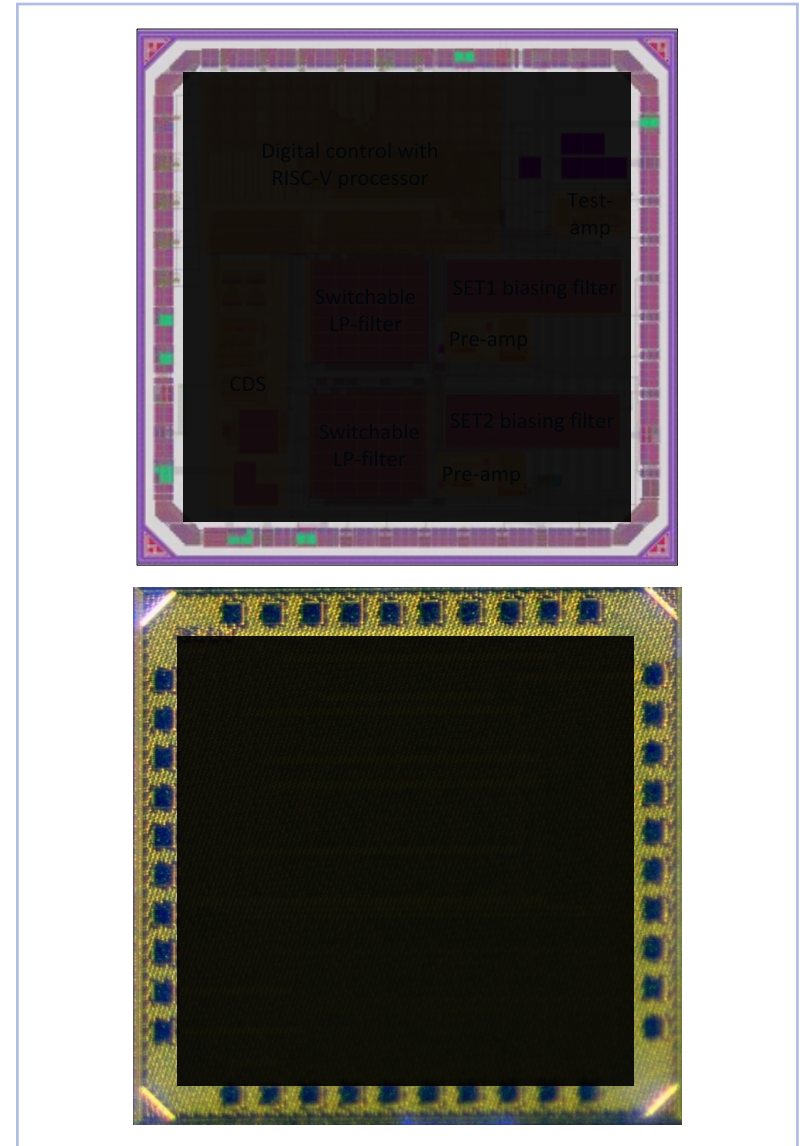
- Write & read IC config regs
- Configuration of IC blocks



POWER DRAW IN PADFRAME

Padframe IP Considerations

- Padframe IP is not made for cryo. temperature
- **Analog pads** are good
 - Typically less leakage in ESD structures
- **Digital pads:**
 - Functionality (mostly fine)
 - even with complex internal circuitry
 - Power (every μW counts at mK)
 - Consider internal power OK generation
 - May generate internal bias voltages (e.g. for IO \leftrightarrow core voltage levelshifter)

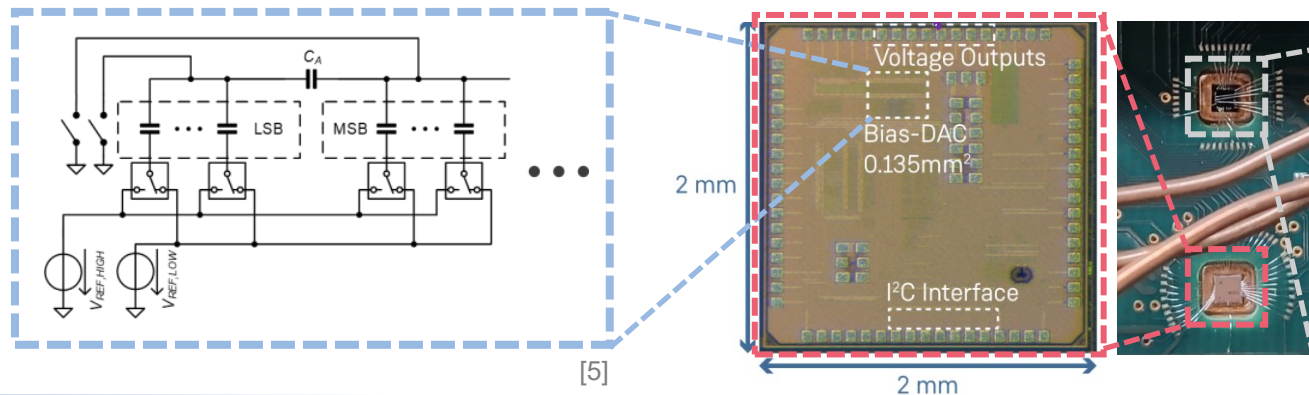


CRYOGENIC INTEGRATED CIRCUITS

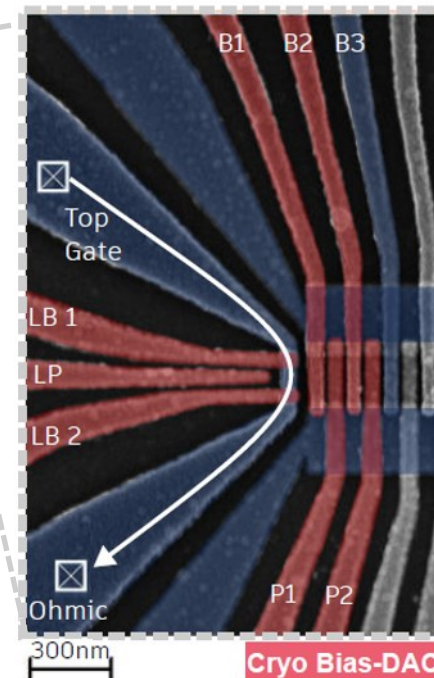
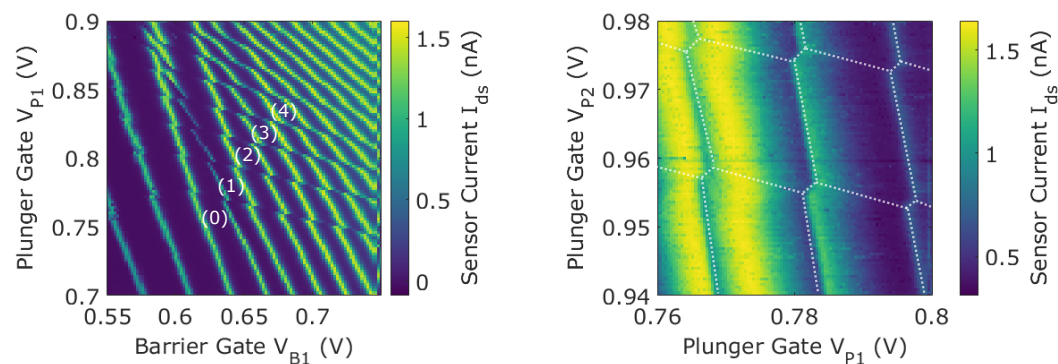
Qubit DC Biasing



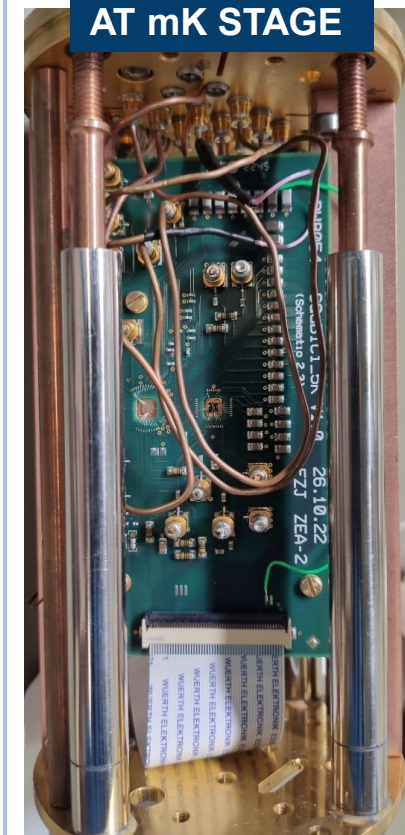
CO-INTEGRATION BIAS DAC WITH Si / SiGe QUBIT



CHARGE SENSING OF SINGLE AND DOUBLE QUANTUM DOT



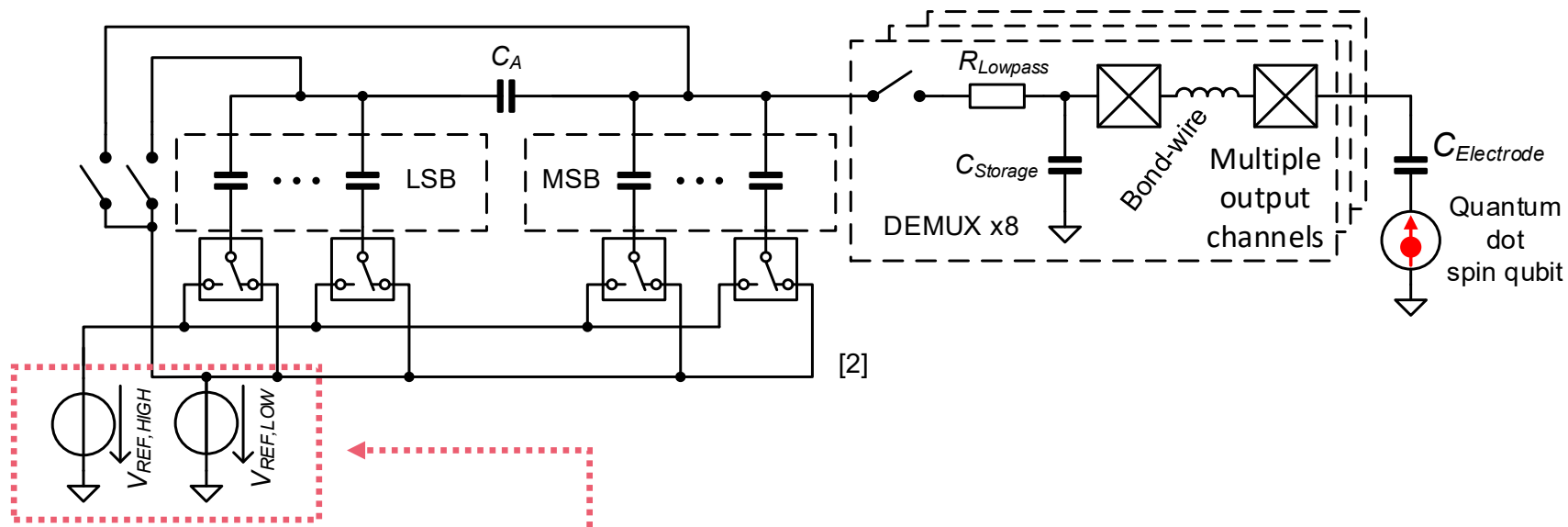
CRYO SETUP AT mK STAGE



- [5] P. Vliex et al., "Bias Voltage DAC Operating at Cryogenic Temperatures for Solid-State Qubit Applications," IEEE Solid-State Circuits Letters, 2020
 [6] L. Schreckenberget al., "SiGe Qubit Biasing with a Cryogenic CMOS DAC at mK Temperature," ESSCIRC 2023

BIAS DAC

Charge-Redistribution Topology

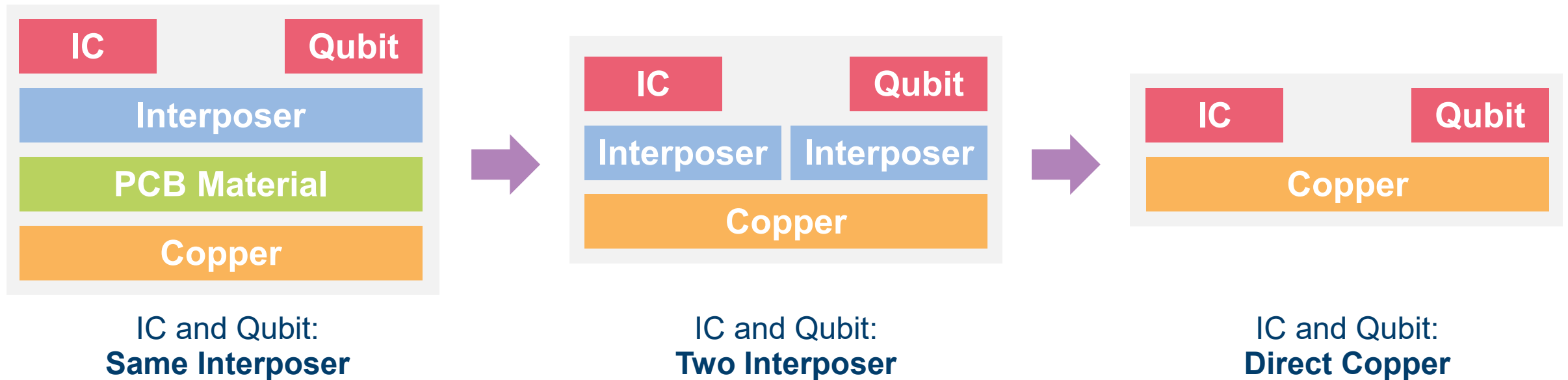


- Negligible static power dissipation
- Low thermal noise at cryo. T : $\bar{v}_N^2 = \frac{k_B \cdot T}{C}$
- No output buffer needed
→ Reduce power and noise
- Coarse tuning by on-chip MUX^[2]
→ Reduce power and increase resolution
→ But need for calibration
- Multiple output channels per DAC

[5] P. Vliex et al., "Bias Voltage DAC Operating at Cryogenic Temperatures for Solid-State Qubit Applications," IEEE Solid-State Circuits Letters, 2020

CRYOGENIC CO-INTEGRATION

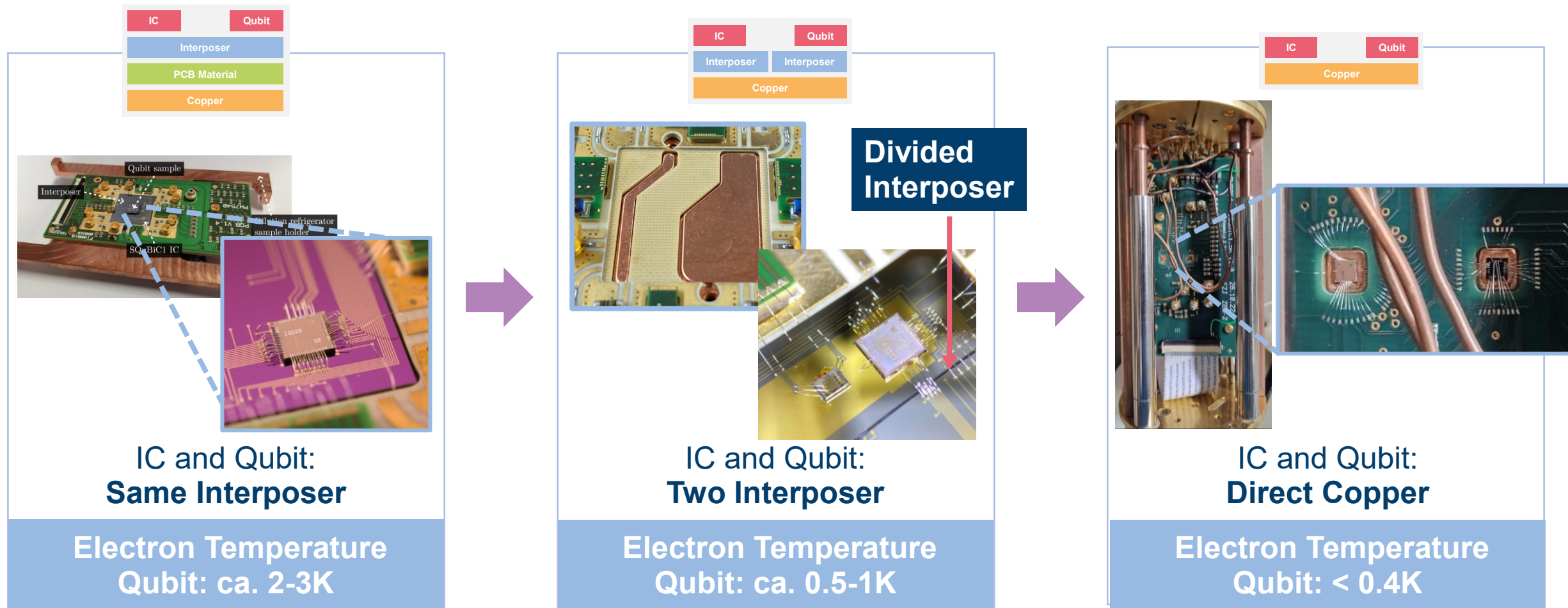
Multiple Approaches



[6] L. Schreckenberget al., "SiGe Qubit Biasing with a Cryogenic CMOS DAC at mK Temperature," ESSCIRC 2023

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Multiple Approaches

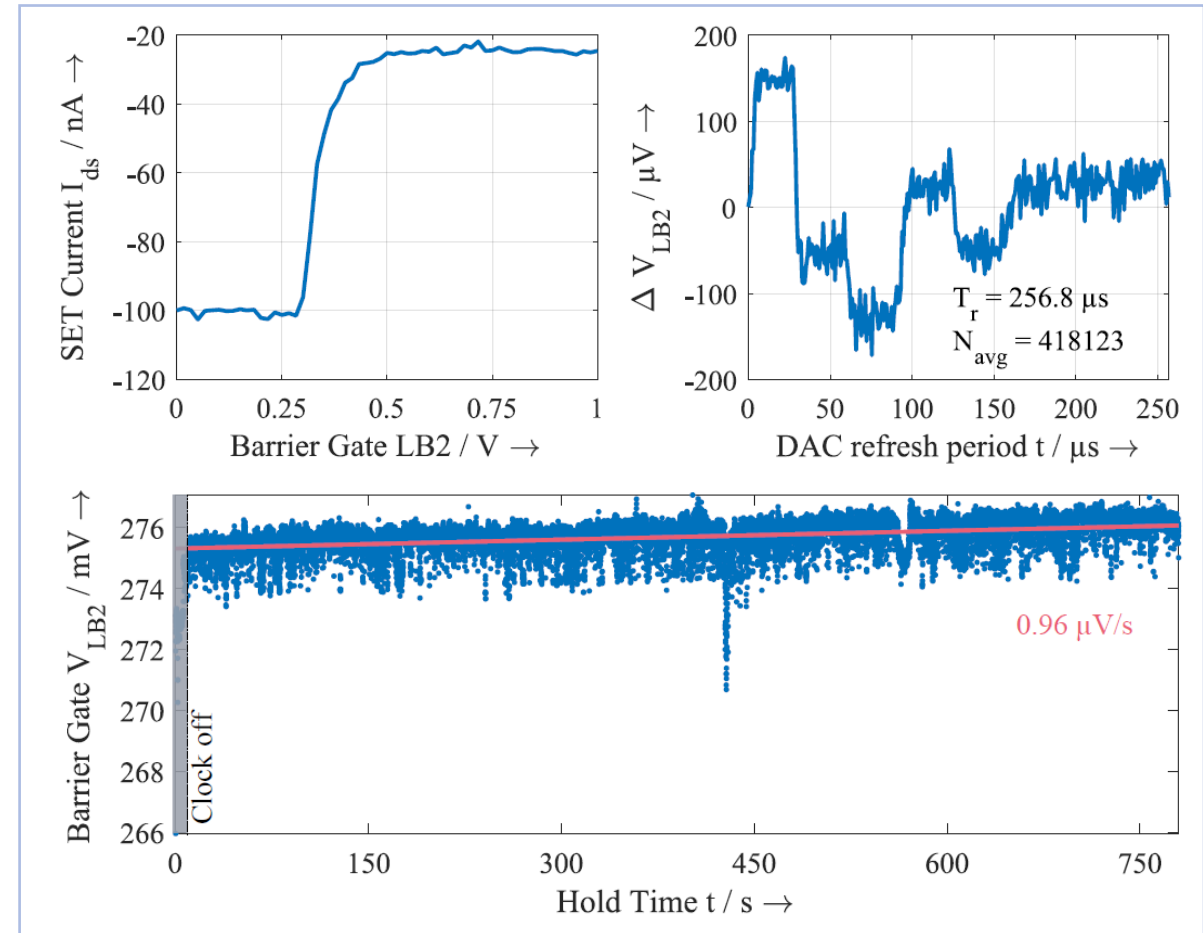
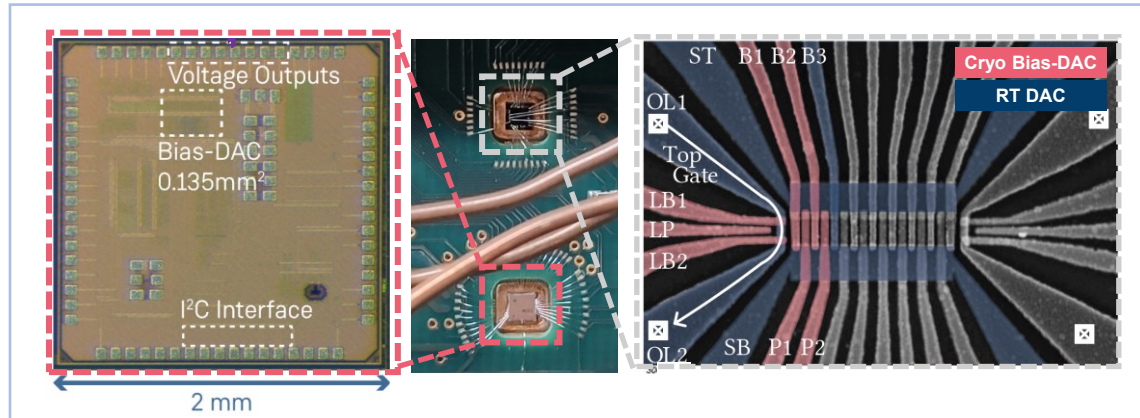


[6] L. Schreckenberget al., "SiGe Qubit Biasing with a Cryogenic CMOS DAC at mK Temperature," ESSCIRC 2023

CRYOGENIC CO-INTEGRATION

Ultra-low Leakage Currents

- Bias DAC cycling through 7 metal electrodes
 - SET used as measurement amplifier
 - Visible cross-talk depending on location
- Leakage rates on metal electrodes meas.
 - 2 pF on-chip cap.; ca. 300 fF off-chip cap.
 - Ultra-low voltage drift of $<1 \mu\text{V/s}$

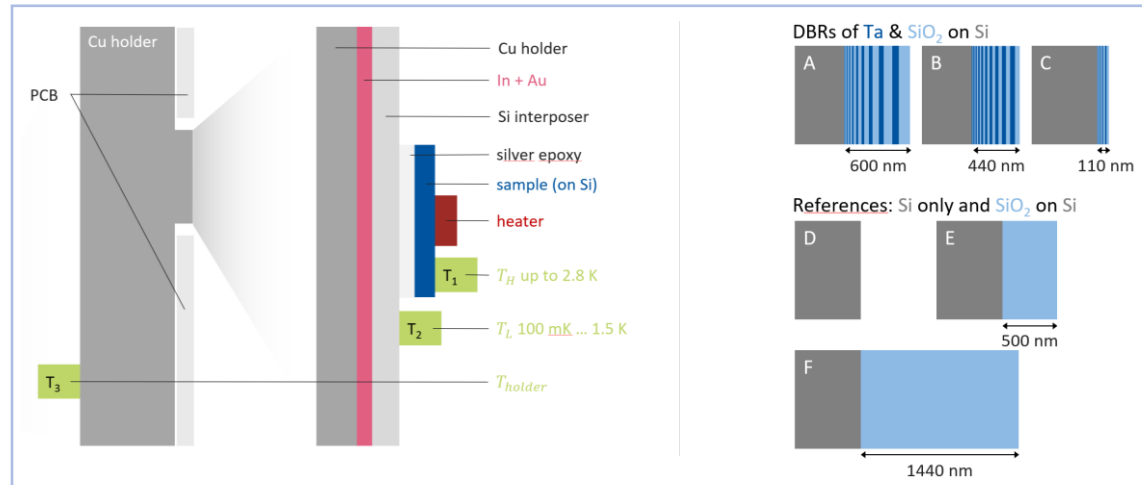


[6] L. Schreckenberget al., "SiGe Qubit Biasing with a Cryogenic CMOS DAC at mK Temperature," ESSCIRC 2023

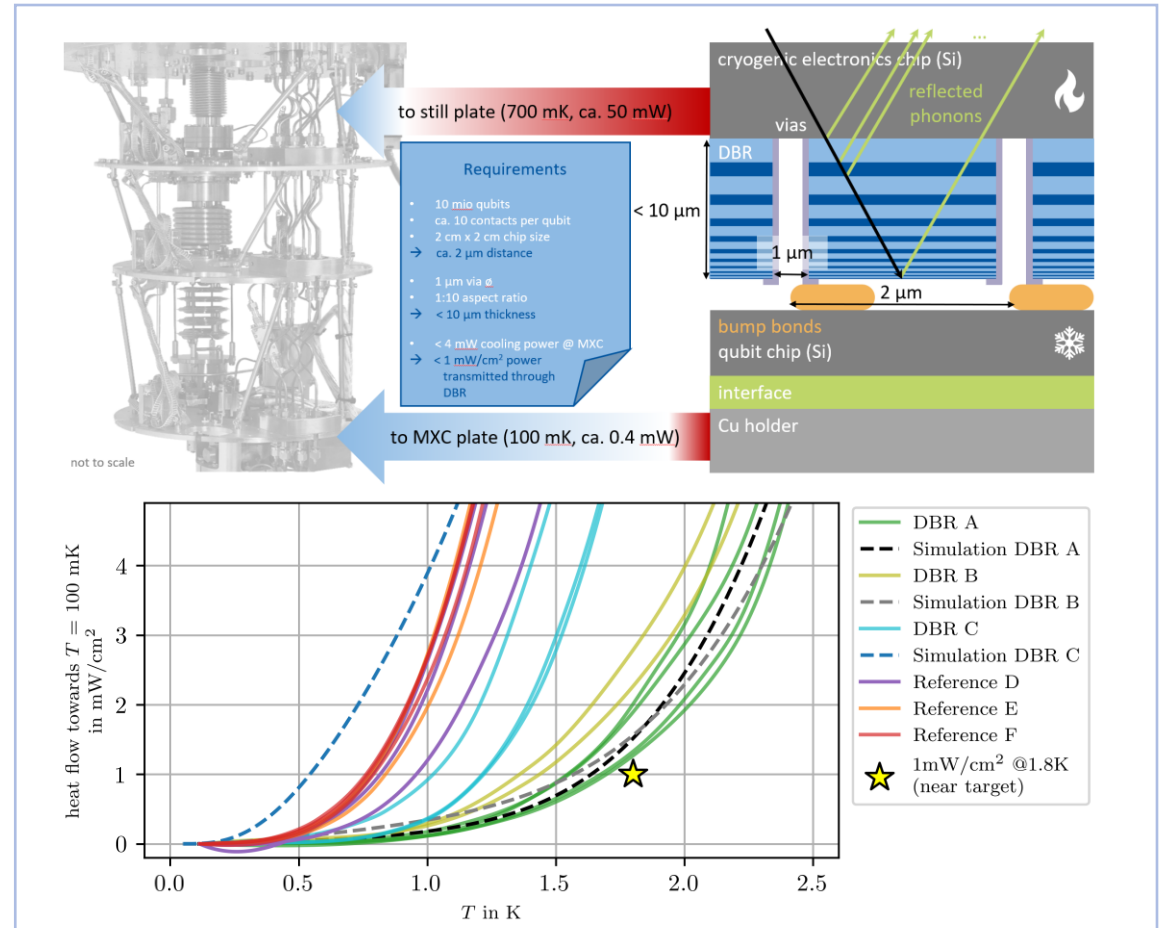
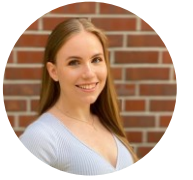
BRAGG REFLECTORS

Thermal Insulation Between Cryogenic Control Electronics and Qubits

- Layers of alternating acoustic impedance
- Broadband constructive interference
→ exponentially increasing thickness
- 600-nm-thick DBR near target
- DBRs insulate much better than the references



[7] I. Sprave et al., "Phononic Bragg Reflectors for Thermal Insulation Between Cryogenic Control Electronics and Qubits", Global Physics Summit 2025, MAR-J19/4

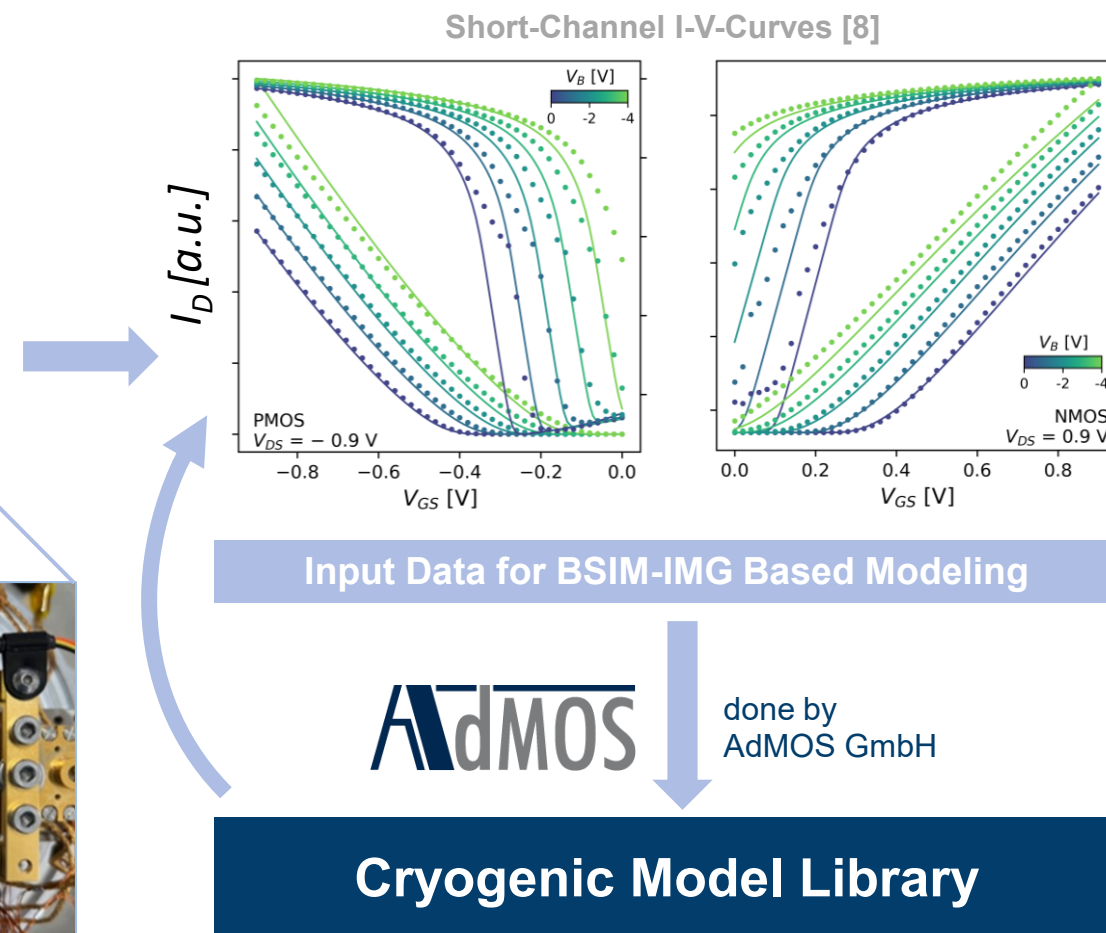
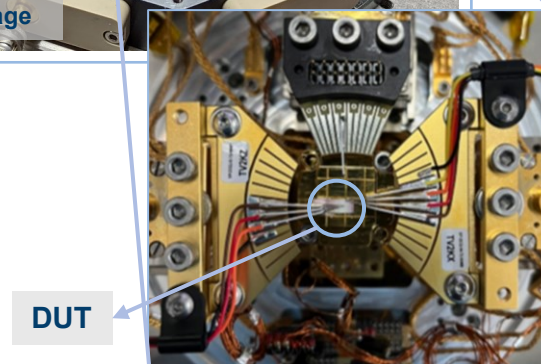
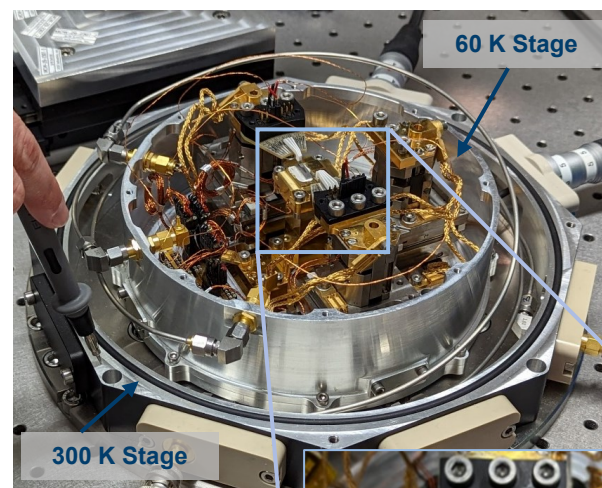
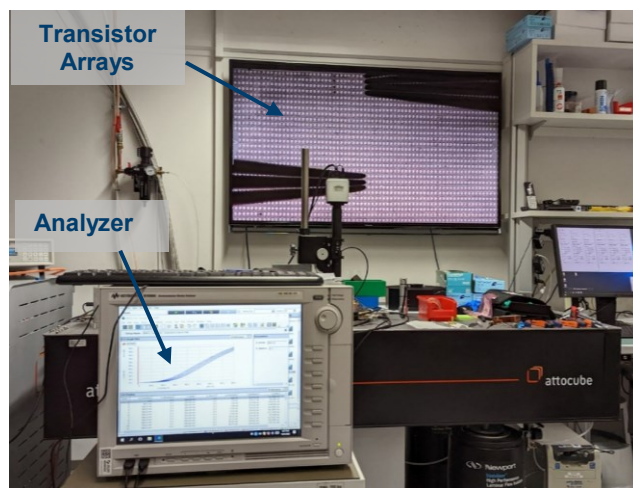


CRYOGENIC MEASUREMENTS

Inputs for a Cryo-PDK for 22 nm CMOS



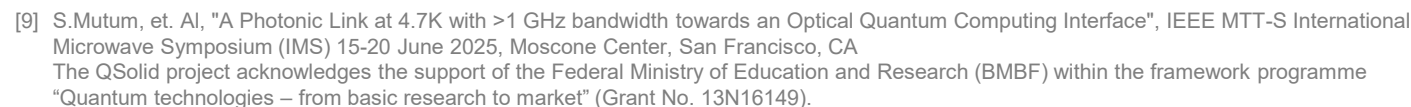
Setup @ ICA | FZJ: $T_{\min} \sim 7 \text{ K}$



[8] Chava, Phanish, et al. "Evaluation of cryogenic models for FDSOI CMOS transistors." 16th IEEE Workshop on Low Temperature electronics. No. FZJ-2024-05369. Zentralinstitut für Elektronik, 2024.
The QSolid project acknowledges the support of the Federal Ministry of Education and Research (BMBF) within the framework programme "Quantum technologies – from basic research to market" (Grant No. 13N16149).

Optical Data and Power Link to Cryo

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and Research

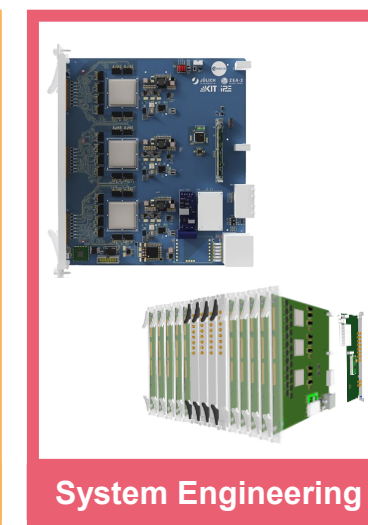
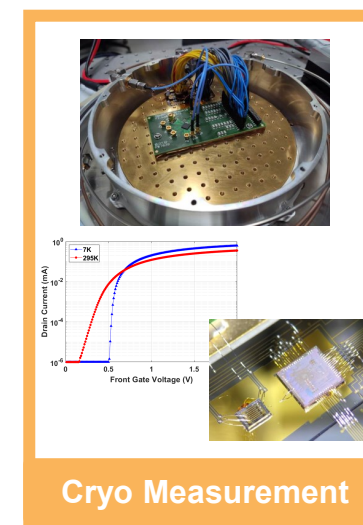
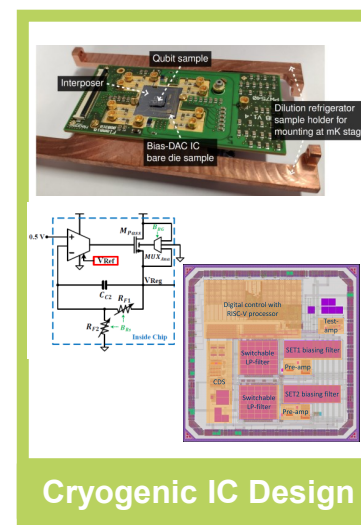
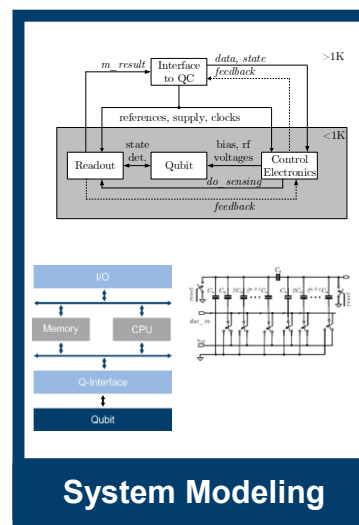
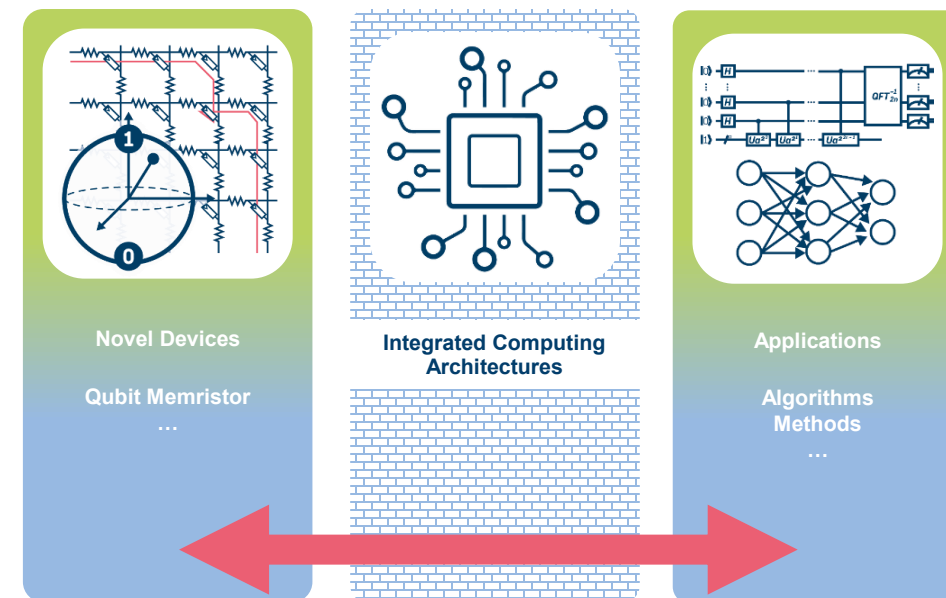


INTERMEDIATE SUMMARY

- **Integrated Computing Architectures**

- Interface between Devices and Applications
- Active in NC and QC

- **QC activities spanning from:**
modeling / specification
over design and verification
up to system integration



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https://social.fz-juelich.de/@fzj_ica

Threads:



www.threads.com/@fzj_ica

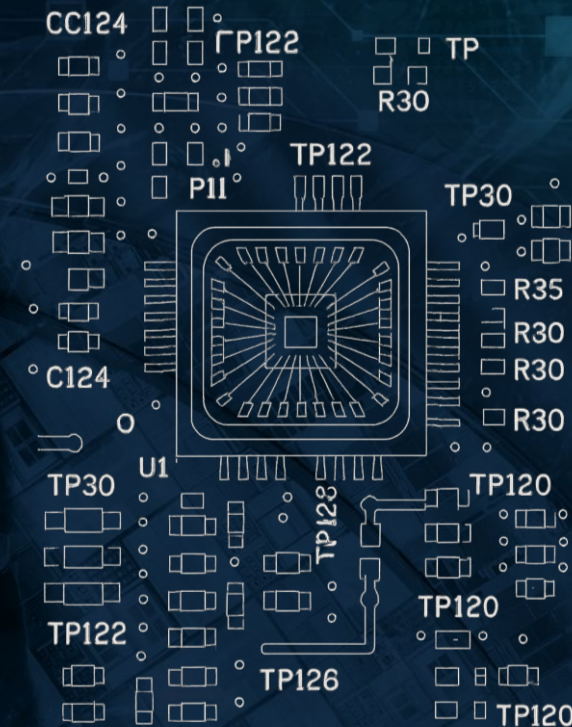
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OUR ROOTS

icecirc is a spin-off of the Institute for Integrated Computing Architectures at Forschungszentrum Jülich which:

- Has 10 years of experience in cryogenic IC design
- Employs state of the art semiconductor technology
- Has demonstrated integration of cryo electronics with qubits [1]



[1] Schreckenberget al. "SiGe Qubit Biasing with a Cryogenic CMOS DAC at mK Temperature", 2023.